

SOIPIX 量子イメージング研究会 2024

# PN-Body Tied SOI-FET 及び Cyro-CMOSの研究進捗

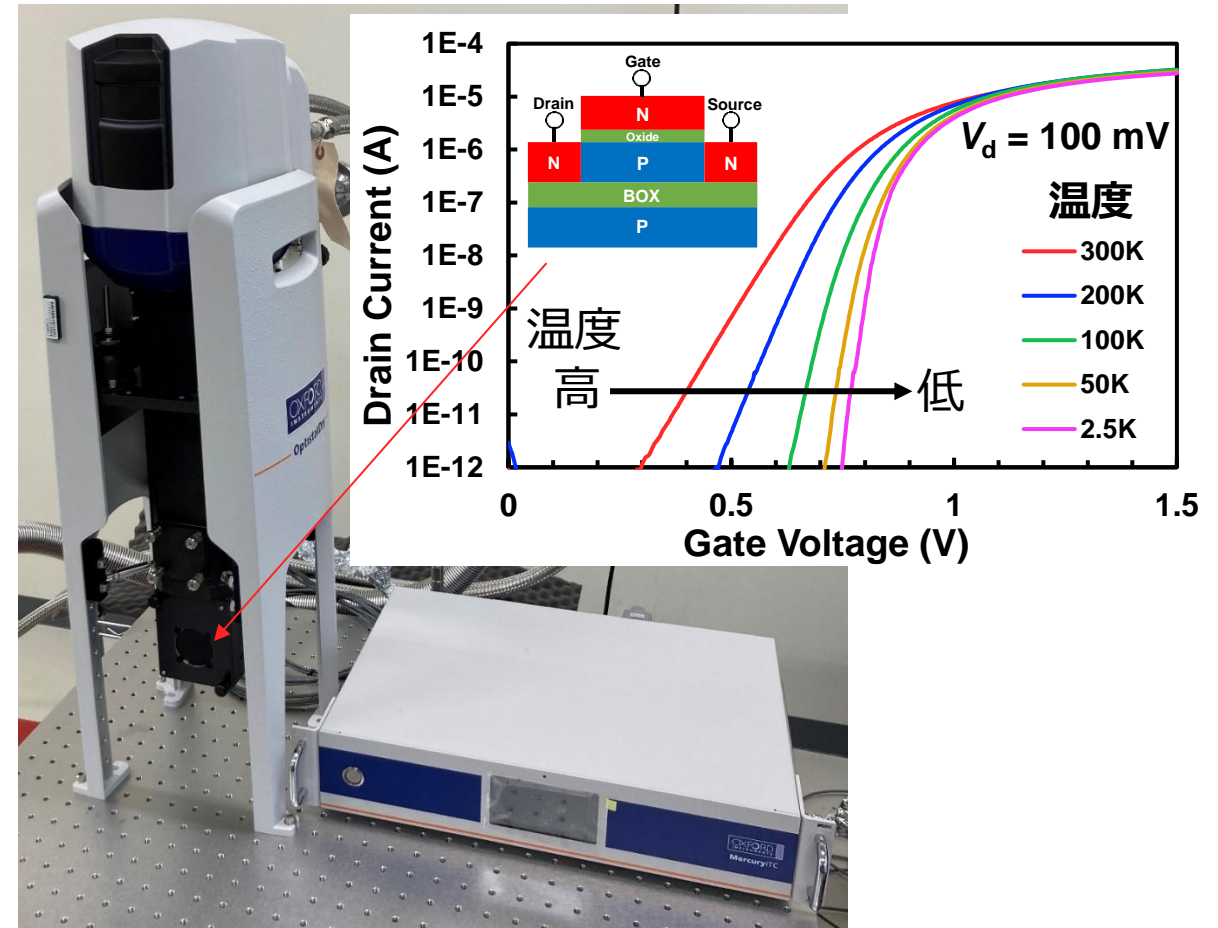
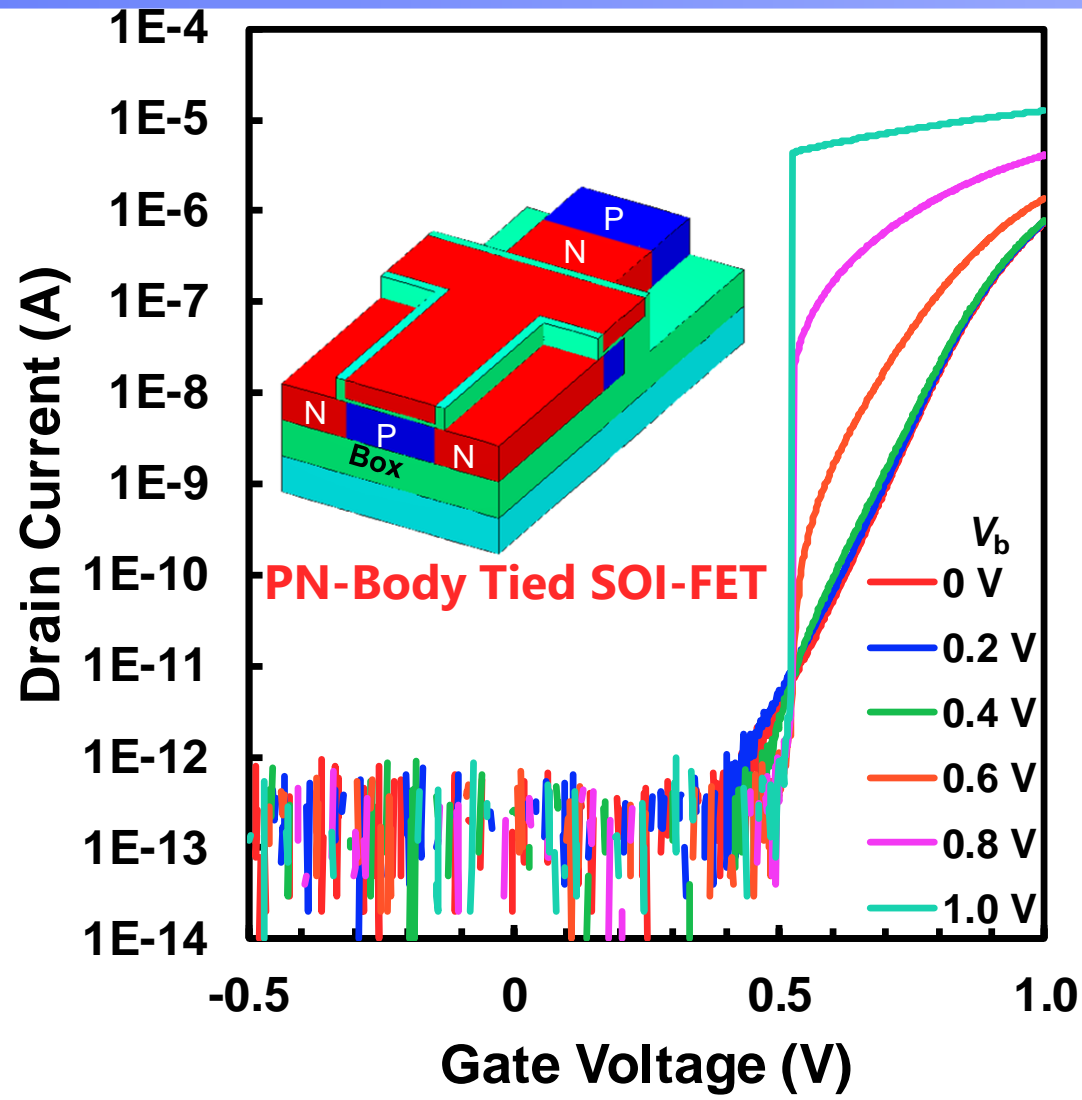
金沢工業大学 森 貴之, 井田 次郎



**KIT**

Kanazawa Institute  
of Technology

# 研究内容



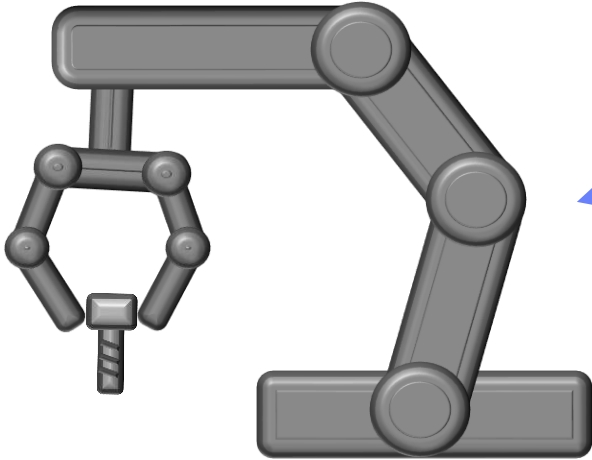
Steep Slope DeviceであるPN-Body Tied SOI-FETと極低温下のSOI MOSFETについて研究  
(Cryo-CMOS)

# PN-Body Tied SOI-FET

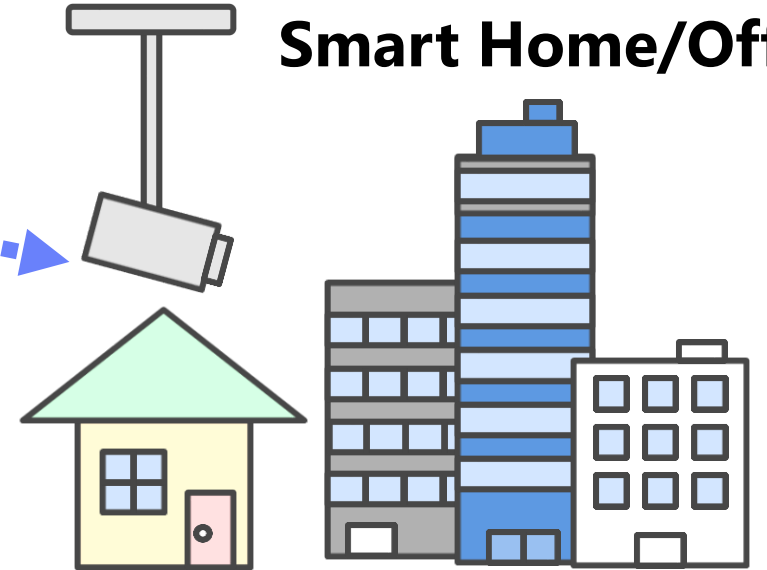
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# 研究背景

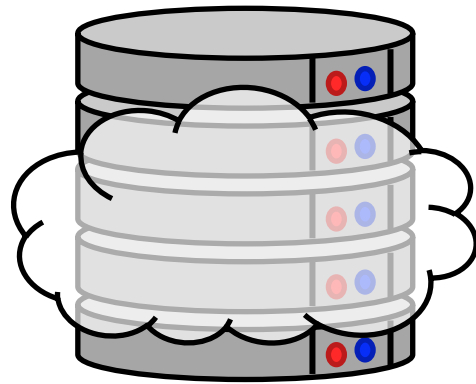
## Factory Automation



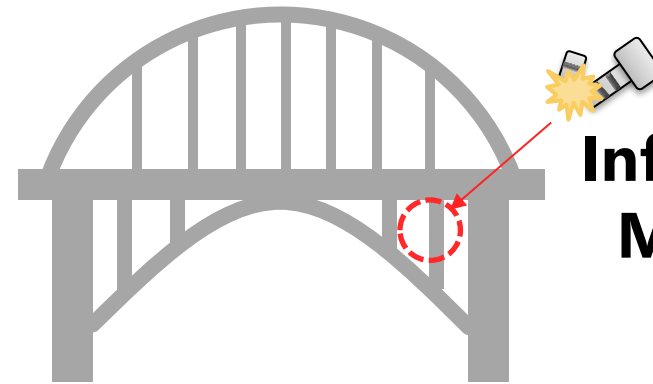
## Smart Home/Office



## Cloud Server



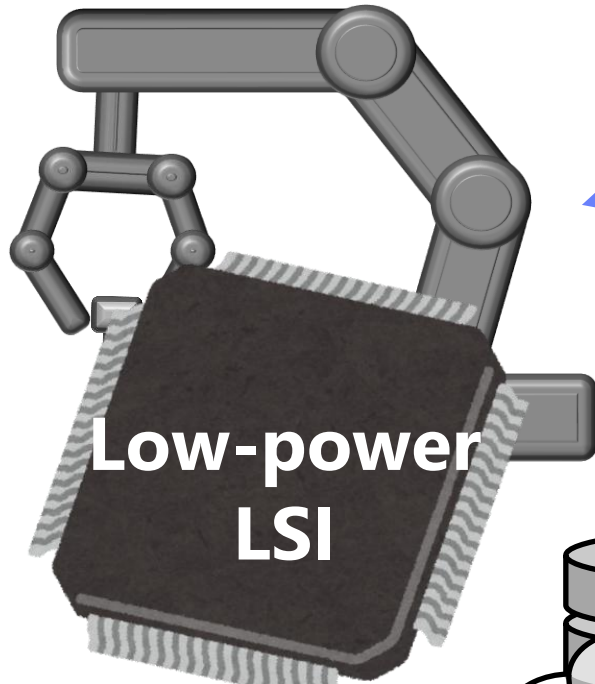
## Infrastructure Monitoring



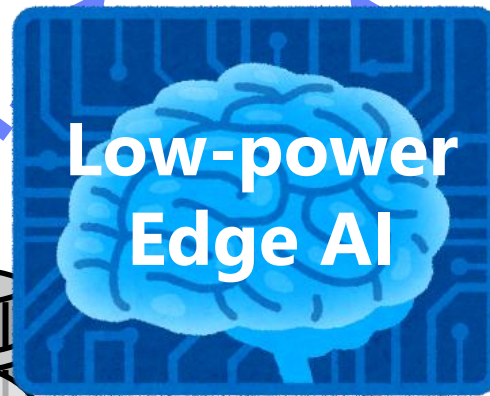
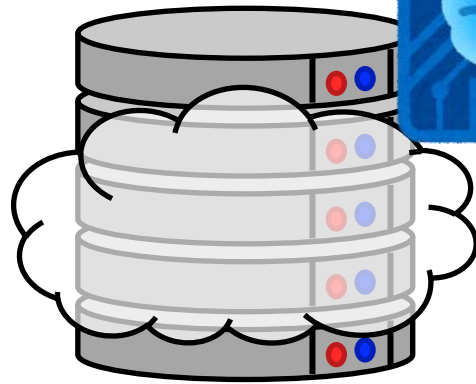
**Everything connects to the Internet.**

# 研究背景

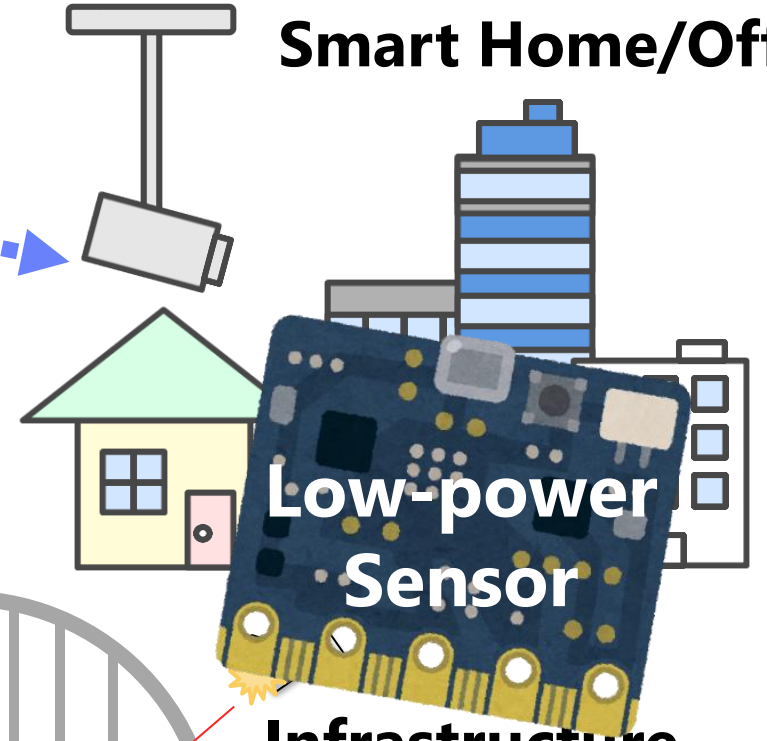
## Factory Automation



Cloud Server



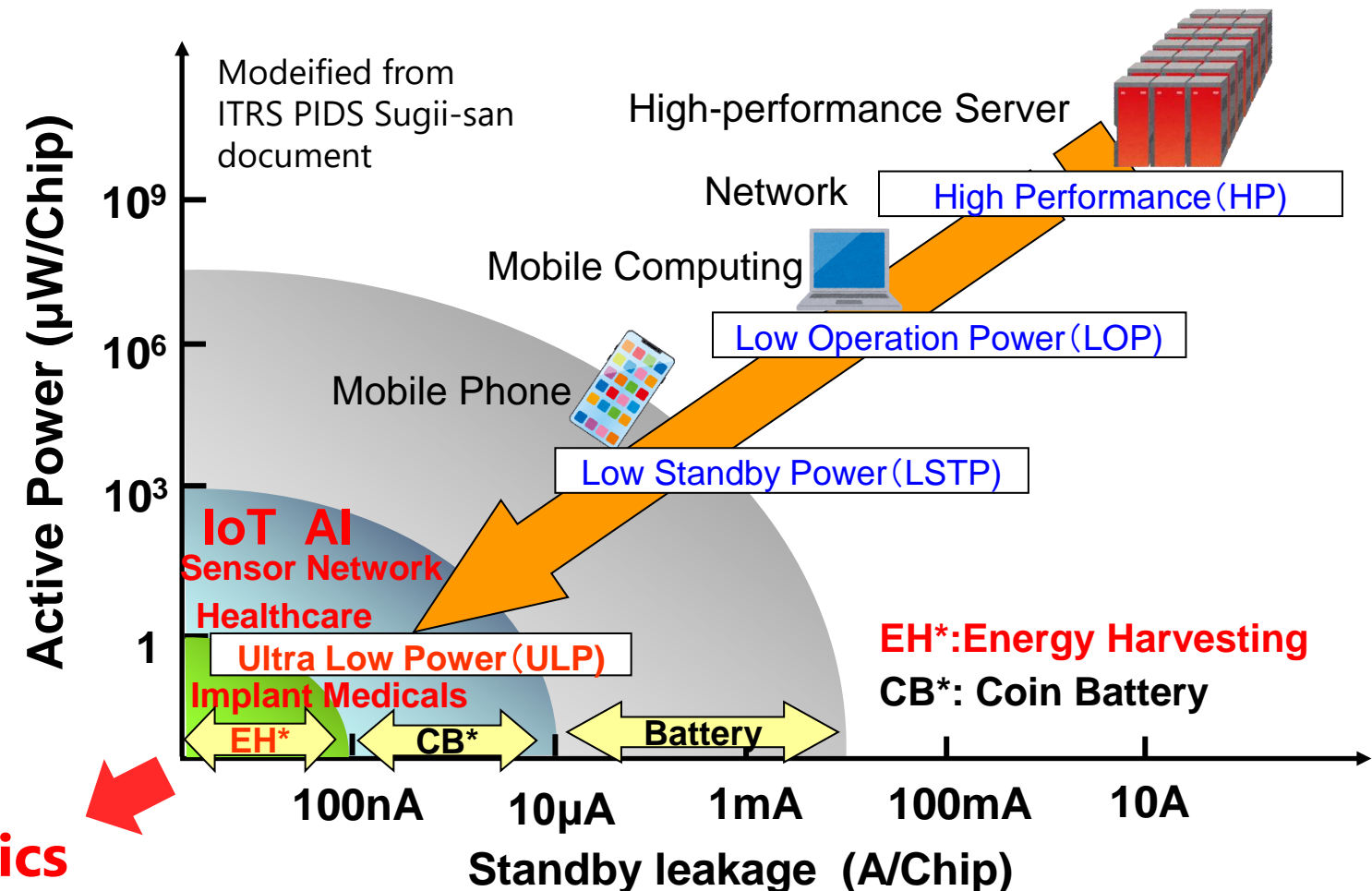
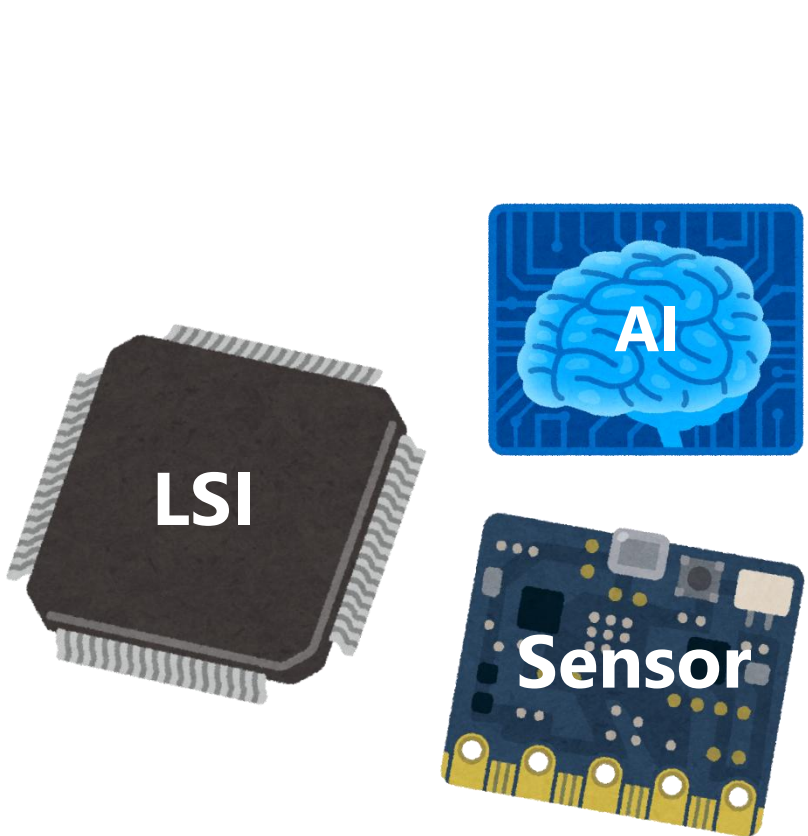
## Smart Home/Office



Infrastructure Monitoring

Everything connects to the Internet.

# 極低消費電力LSIの必要性

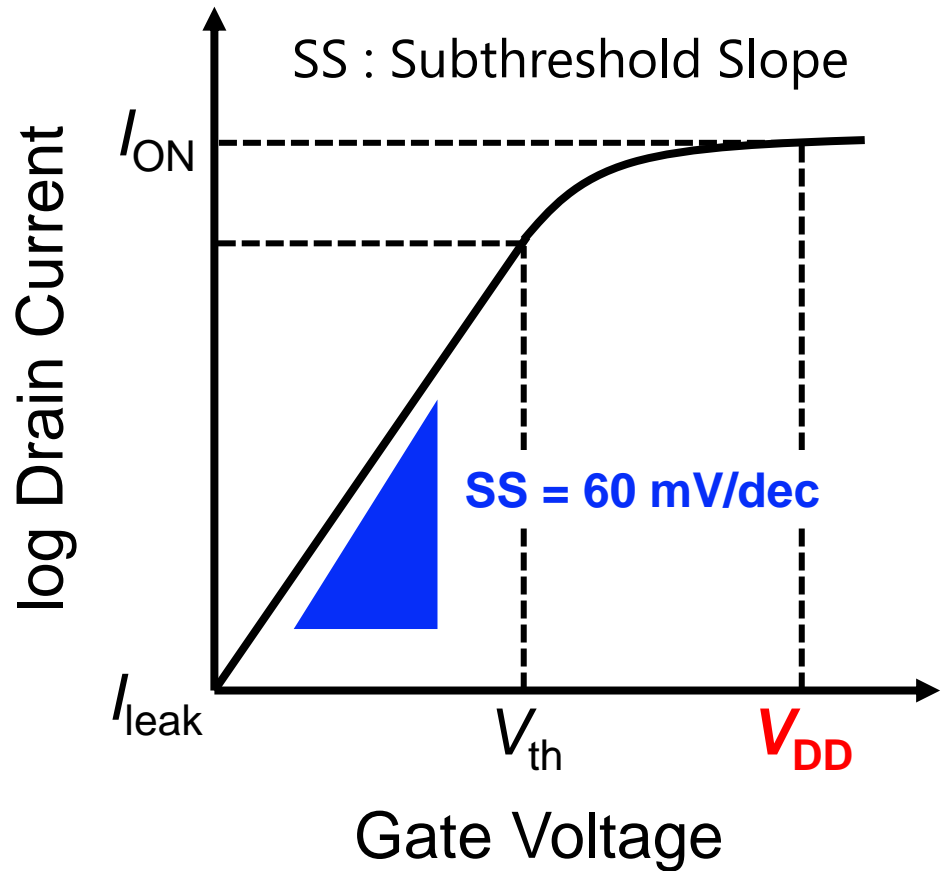


**Micro & Nano Watt Electronics**

大規模集積回路 (Large-Scale Integrated circuit : LSI)を  
極低消費電力 (バッテリーレス) で動作させなければならない

# 極低消費電力化に向けた MOSFET SS急峻化の必要性

## Low supply voltage ( $V_{DD}$ ) needs for low-power LSI



### Power consumption of LSI

$$P_{active} \propto f \cdot C_{load} \cdot V_{DD}^2$$

$$P_{standby} \propto I_{leak} \cdot V_{DD}$$

### Conventional MOSFET

### fundamental SS limitation (room temp.)

$$S = n \frac{kT}{q} \ln 10 \approx \underline{60 \text{ (mV/dec)}}$$

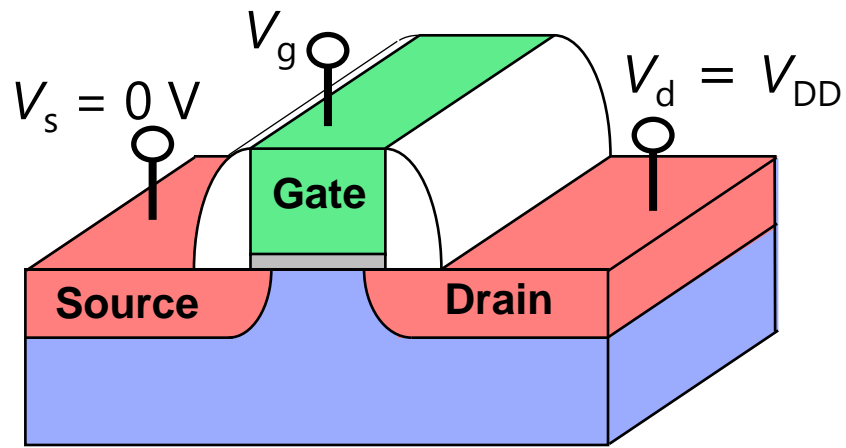
$$n = 1 + \frac{C_D}{C_{ox}}$$



Theoretical Limit

LSIの極低消費電力化にはSSの更なる急峻化が必要だが  
従来のMOSFETには SSの理論下限が存在

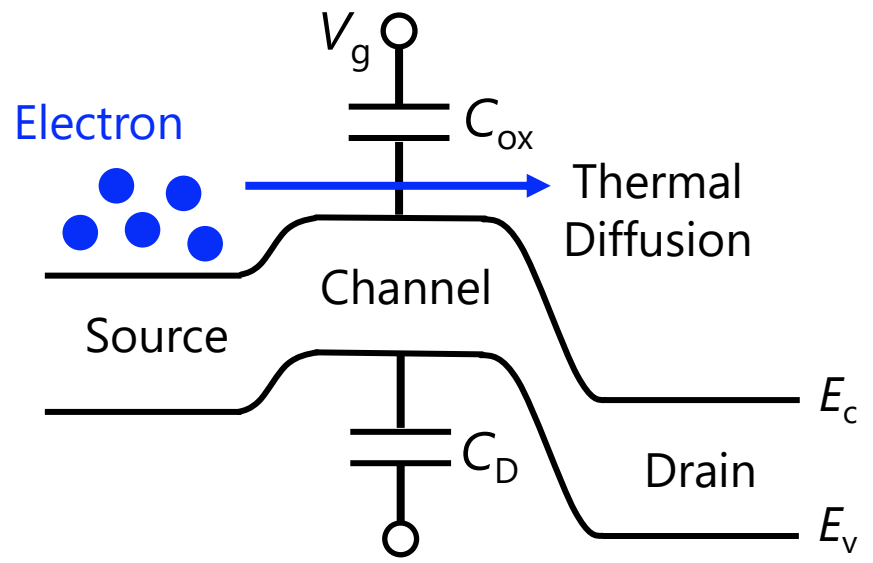
# 極低消費電力化に向けた MOSFET SS急峻化の必要性



## Power consumption of LSI

$$P_{\text{active}} \propto f \cdot C_{\text{load}} \cdot V_{DD}^2$$

$$P_{\text{standby}} \propto I_{\text{leak}} \cdot V_{DD}$$



## Conventional MOSFET fundamental SS limitation (room temp.)

$$S = n \frac{kT}{q} \ln 10 \approx \underline{60 \text{ (mV/dec)}}$$

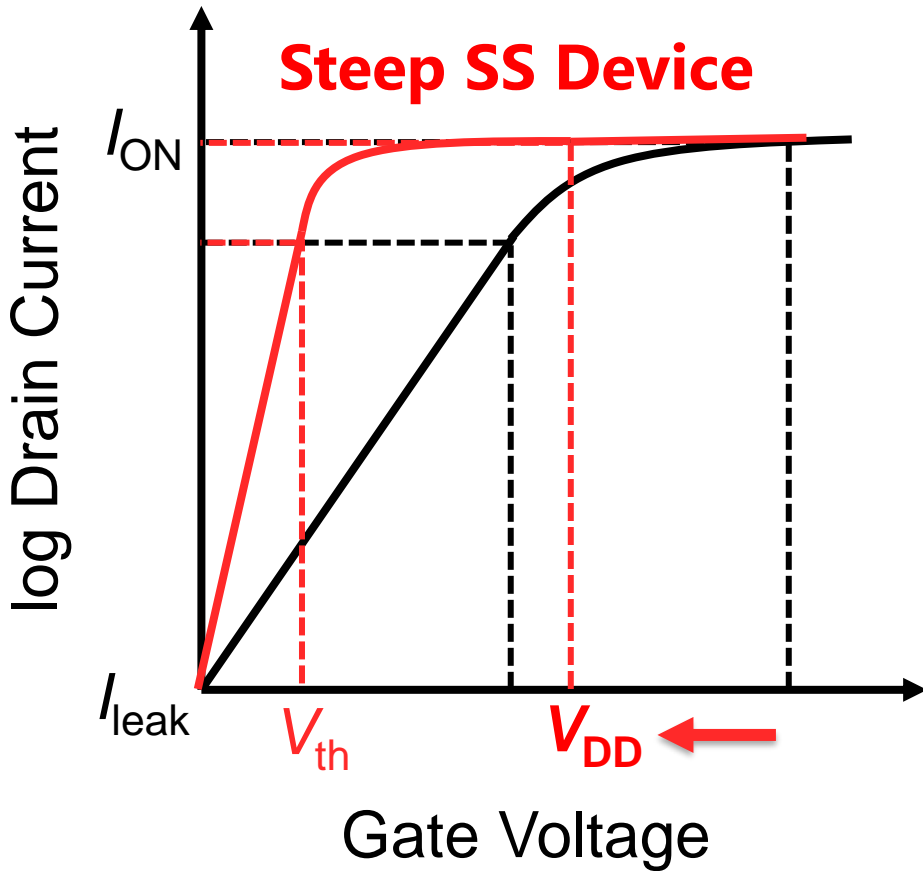
$$n = 1 + \frac{C_D}{C_{ox}}$$

**Theoretical Limit**

**LSIの極低消費電力化にはSSの更なる急峻化が必要だが  
従来のMOSFETにはSSの理論下限が存在**



# Steep subthreshold slope device



## Power consumption of LSI

$$P_{\text{active}} \propto f \cdot C_{\text{load}} \cdot V_{\text{DD}}^2$$

$$P_{\text{standby}} \propto I_{\text{leak}} \cdot V_{\text{DD}}$$

## Conventional MOSFET

### fundamental SS limitation (room temp.)

$$S = n \frac{kT}{q} \ln 10 \approx \underline{60 \text{ (mV/dec)}}$$

$$n = 1 + \frac{C_D}{C_{\text{ox}}}$$

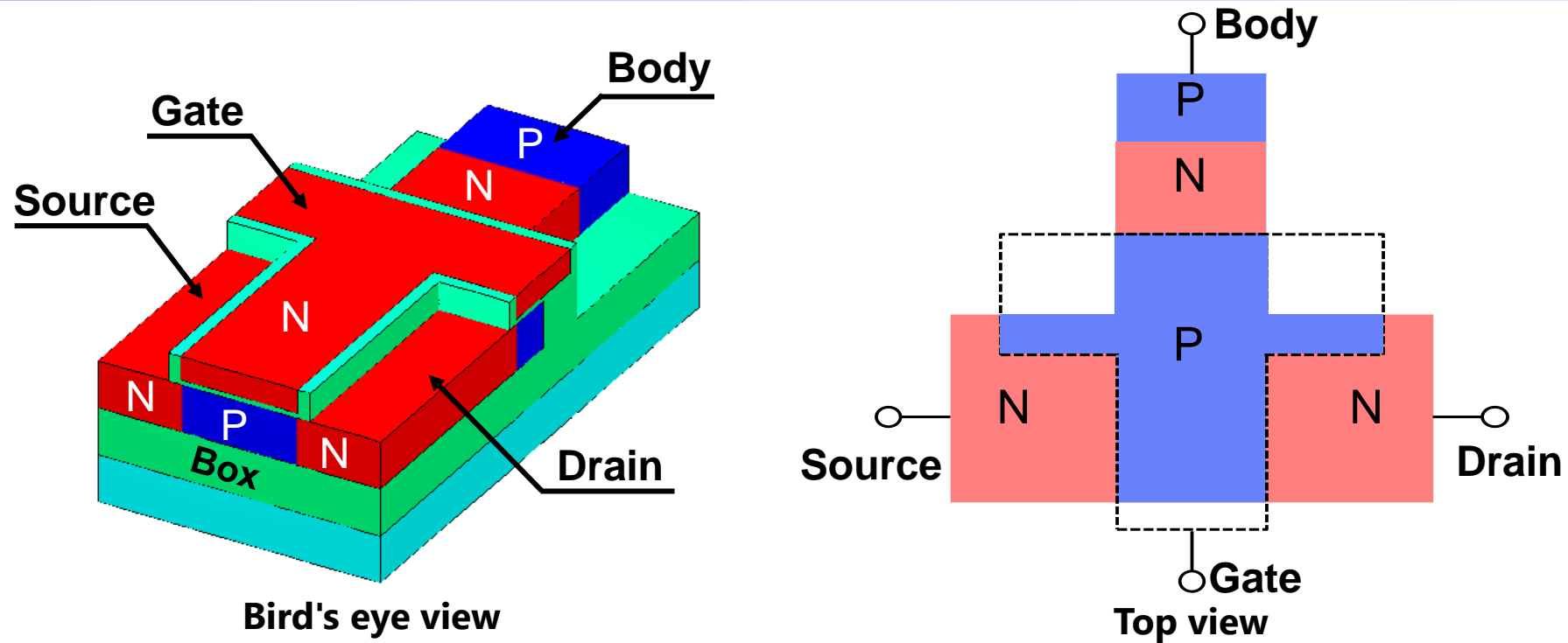


Theoretical Limit

## Steep Subthreshold Slope (SS) Device

従来のMOSFETとは異なる動作原理によるスイッチングが必要

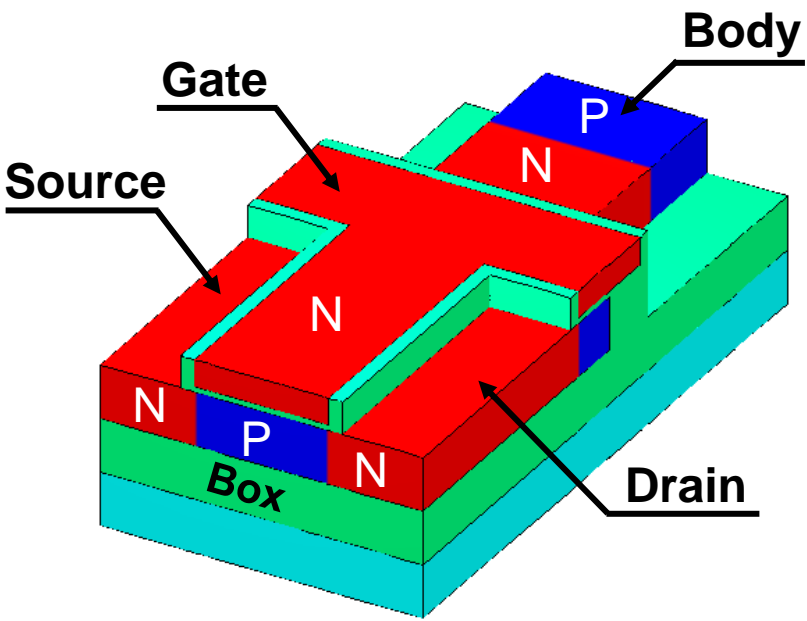
# PN-Body Tied (PNBT) SOI-FET



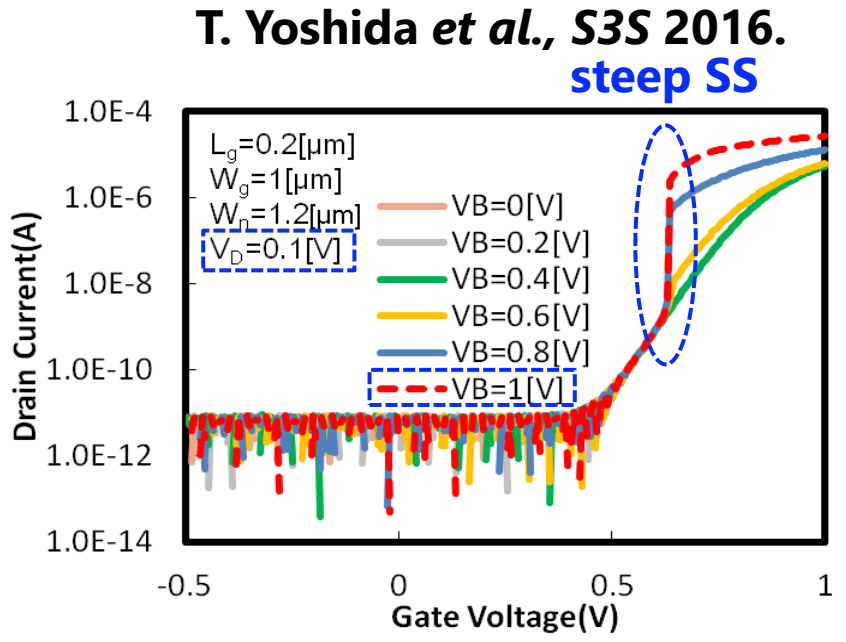
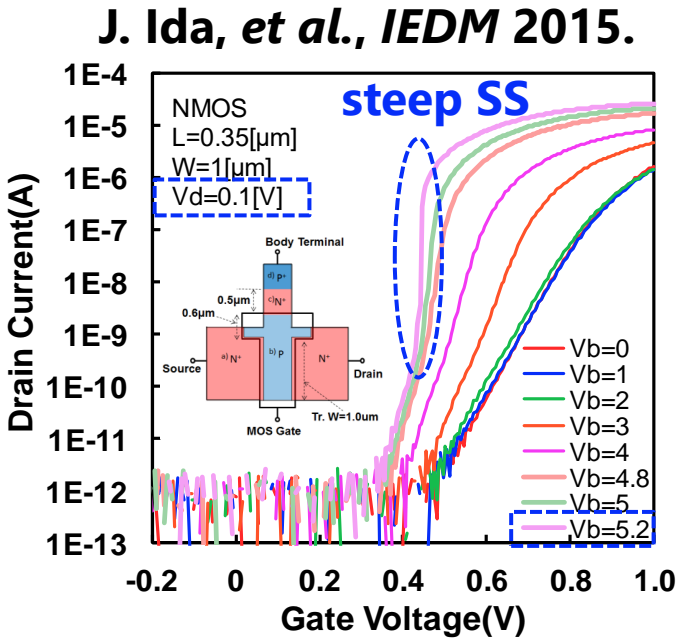
## PNBT SOI-FET

We proposed PN-Body Tied (PNBT) SOI-FET which has a **symmetry S/D** and demonstrated that PNBT SOI-FET has steep SS with **low drain voltage  $V_d$  ( $= 0.1$  V)**.

# PN-Body Tied (PNBT) SOI-FET

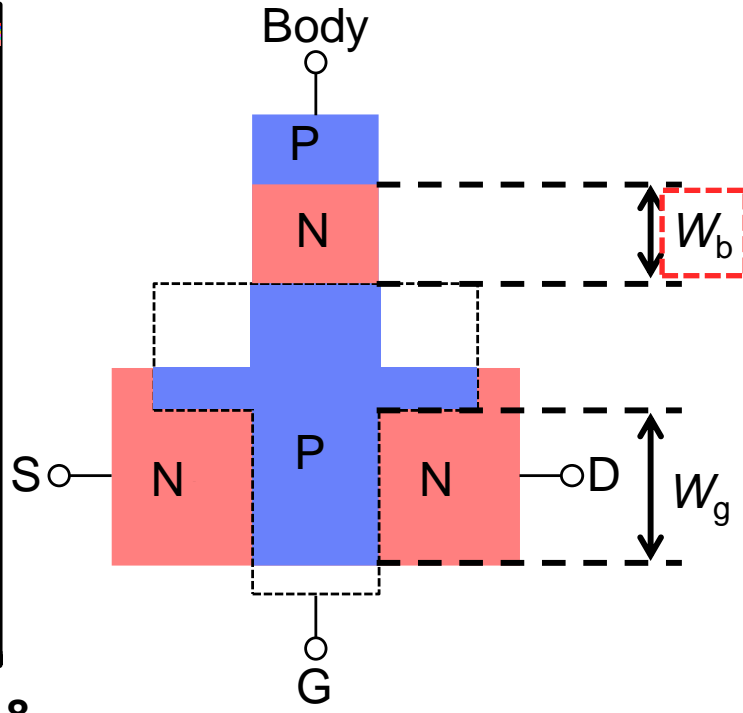
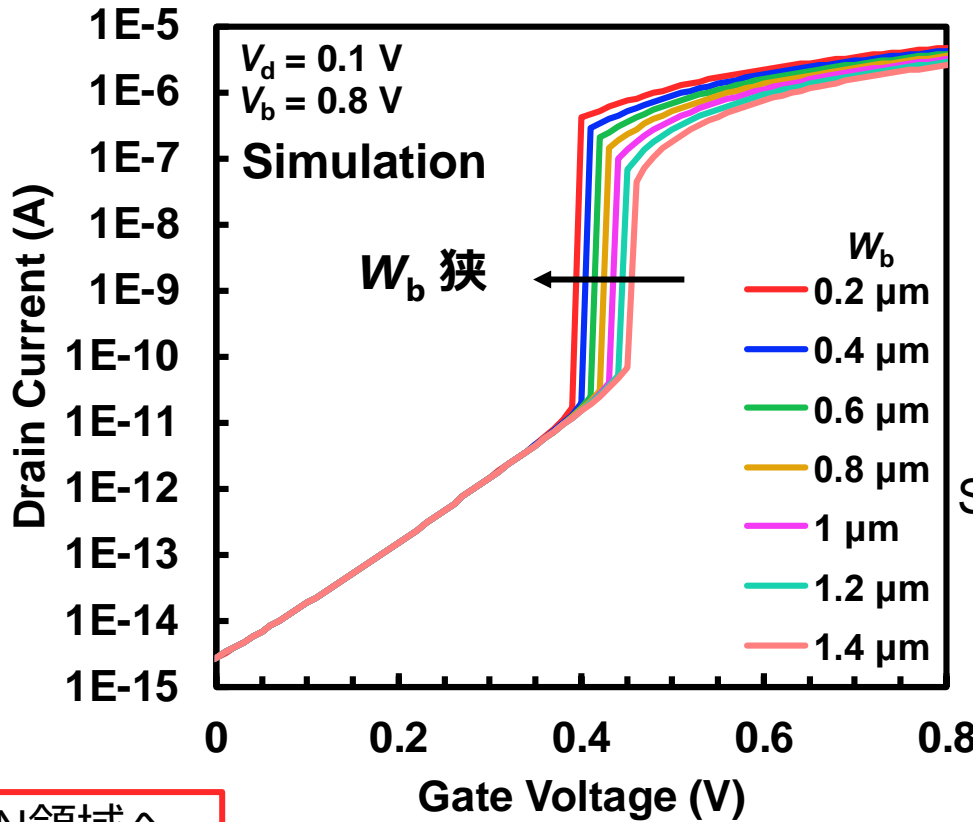
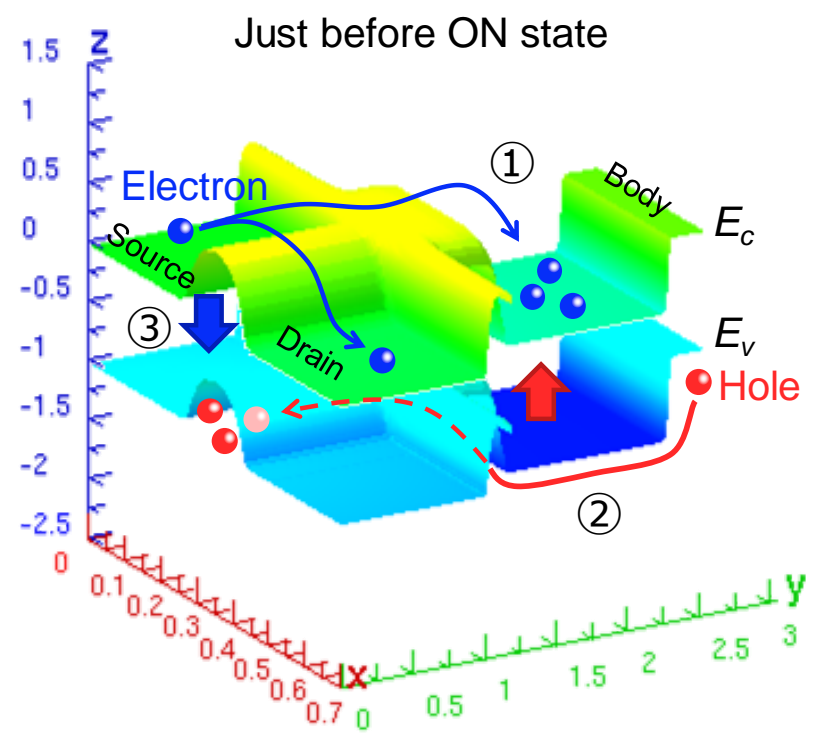


**PNBT SOI-FET**



We proposed PN-Body Tied (PNBT) SOI-FET which has a **symmetry S/D** and demonstrated that PNBT SOI-FET has steep SS with **low drain voltage  $V_d$  (= 0.1 V)**.

# 動作原理・デバイスパラメータ依存性の例



1. 電子がDrain及びBody方向に拡散しN領域へ
2. N領域の電子によってBody-channel間の電位障壁が減少、正孔がchannel下部へ
3. channel下部に蓄積した正孔が Source-Drain/Body間の電位障壁を下げる

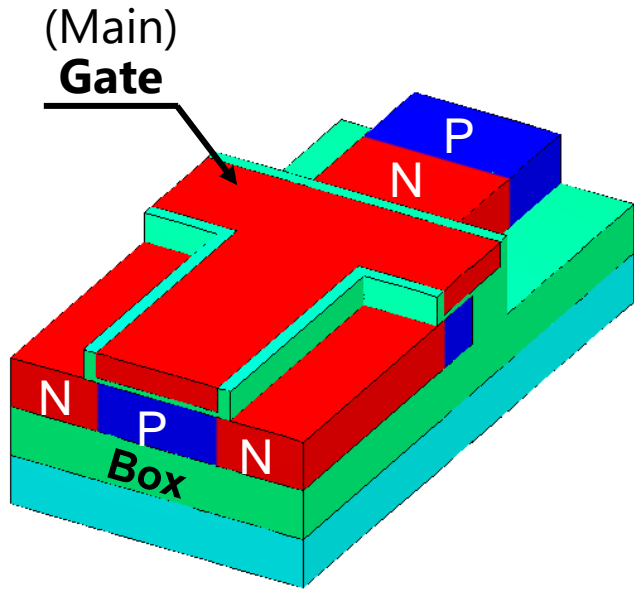
**$W_b$ が狭いほど  $I_{on}/I_{off}$ 比増大かつ低い  $V_g$ で立ち上がる**

T. Mori et al., SSDM, pp. 839–840, Sep. 2018.

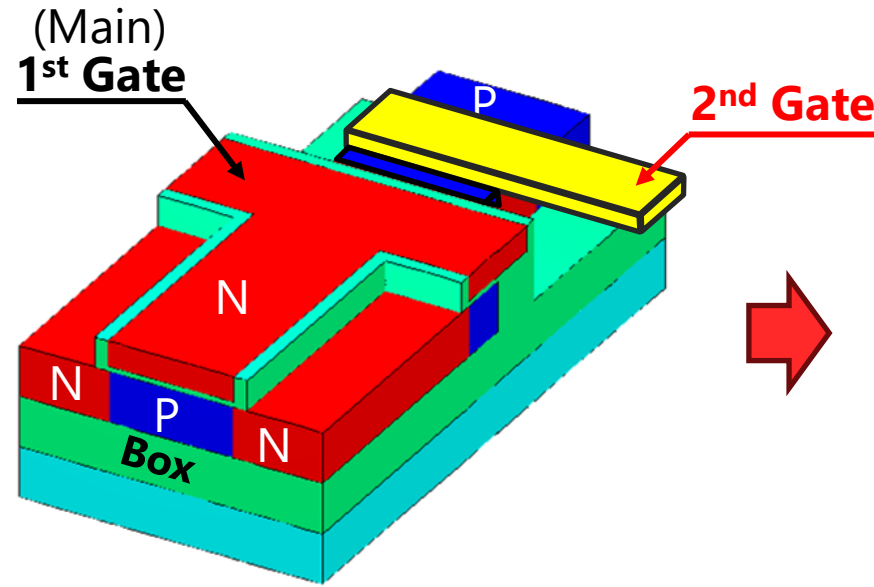
性能改善に向けたデバイス構造、動作原理解明について研究

T. Mori et al., IEEE J. Electron Devices Soc., vol. 6, pp. 1213–1219, Oct. 2018.

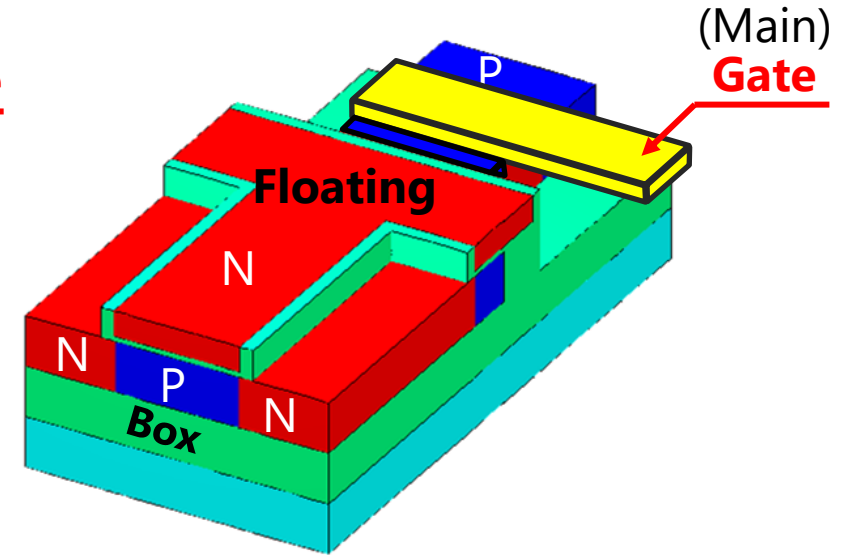
# PNBT SOI-FETの進歩



Single Gate PNBT SOI-FET  
(SG PNBT SOI-FET)



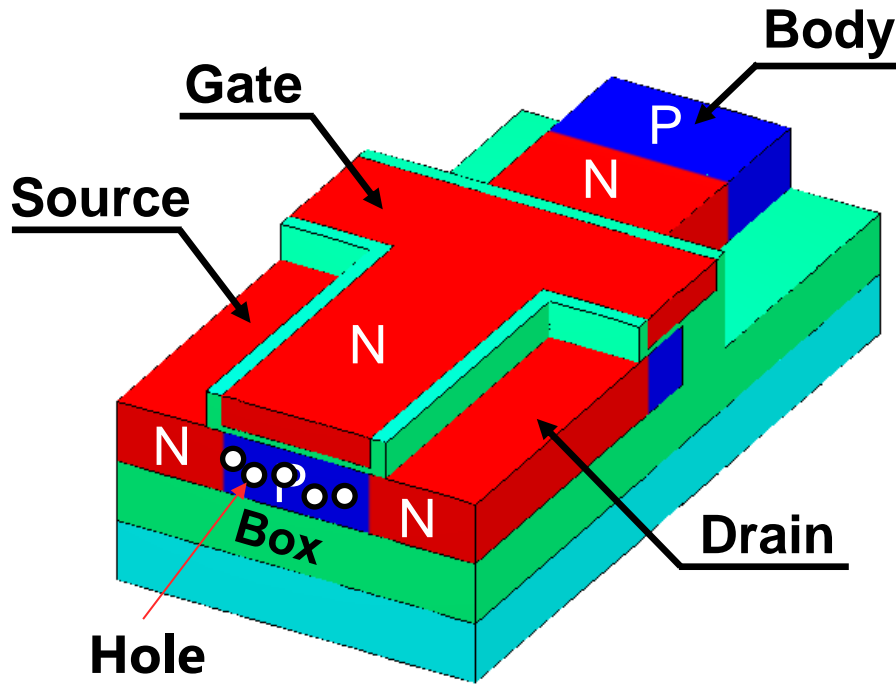
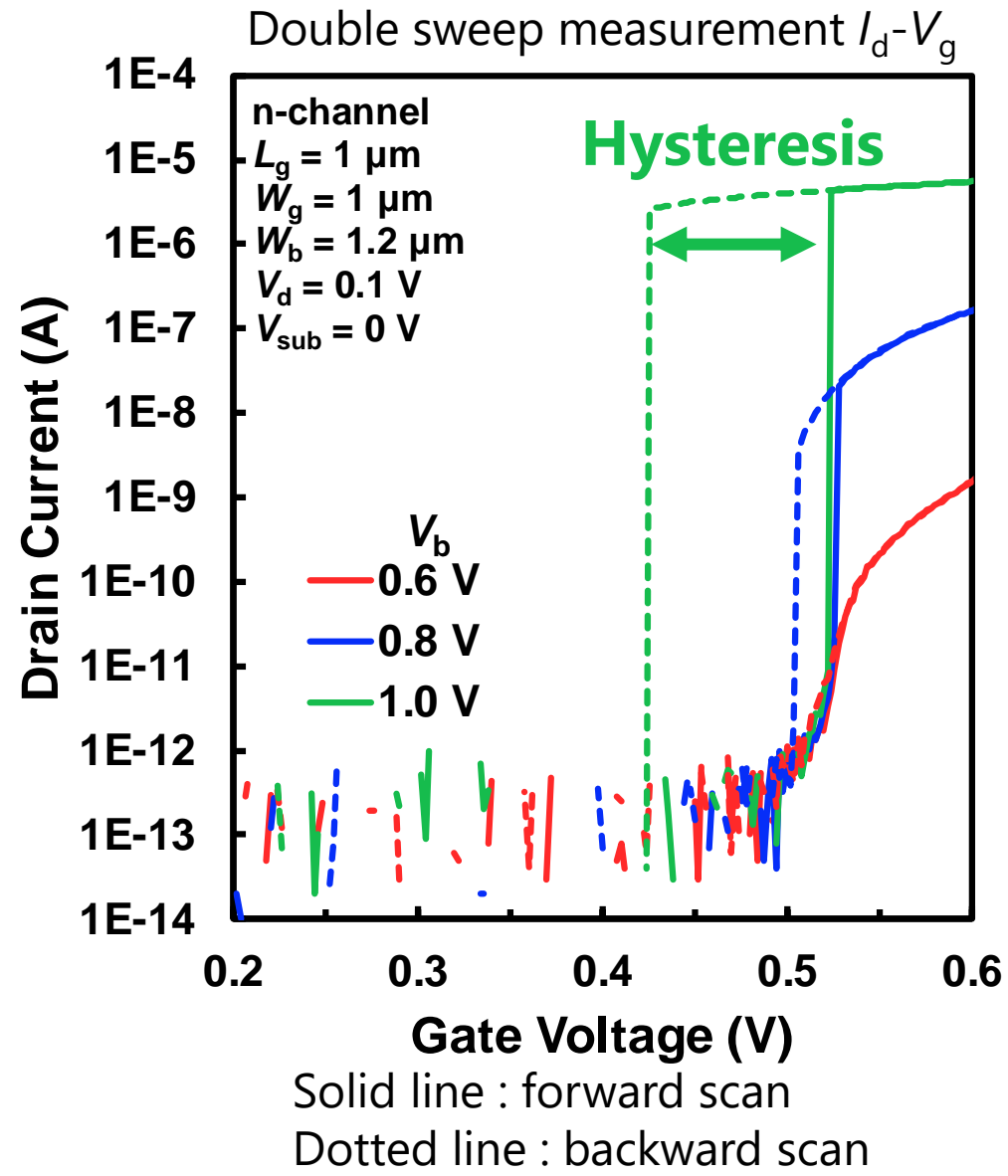
Dual Gate PNBT SOI-FET  
(DG PNBT SOI-FET)



Gate-Controlled Carrier-Injection SOI-Tr  
(GCCI SOI-Tr)

SG・DG PNBT SOI-FETにおけるArイオン注入効果とGCCI SOI-Trについて紹介

# Issue of PNBT SOI-FET | Hysteresis characteristics



**Channel potential is maintained by accumulated carriers.**



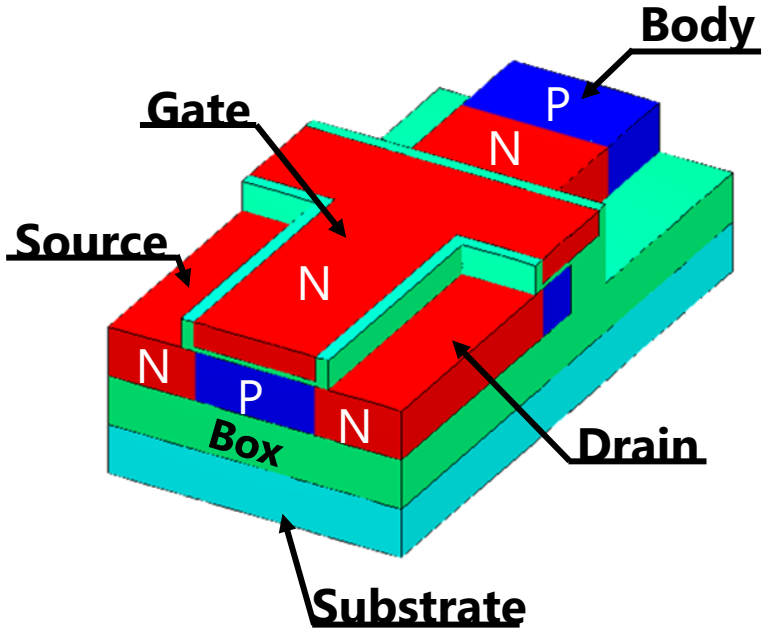
**Hysteresis characteristics appear.**

# Arイオン注入によるヒステリシス制御

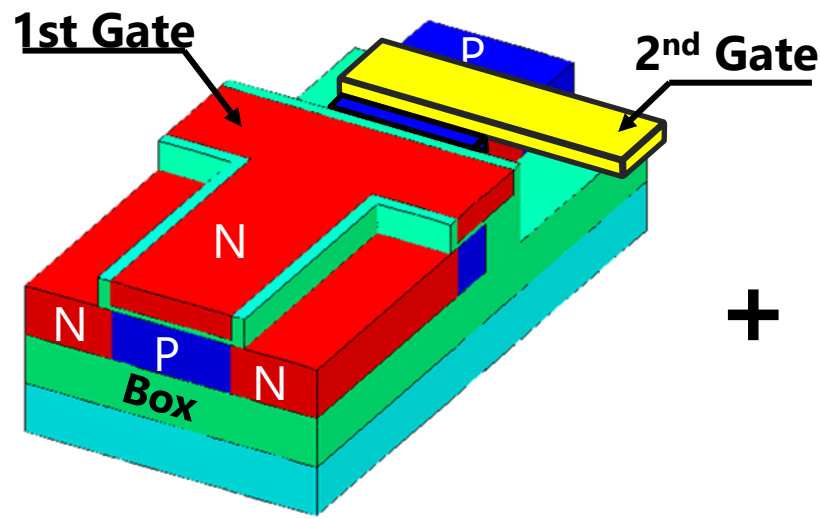
Decreasing (controlling) hysteresis characteristics is necessary.



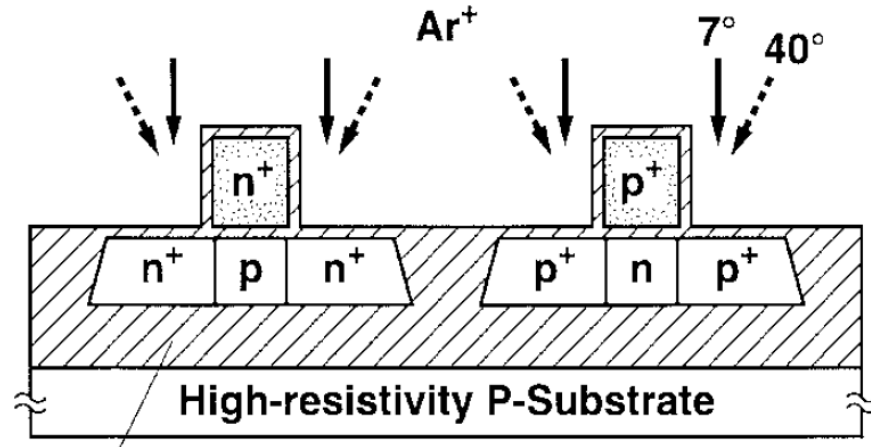
show Ar-ion implantation effect on single-gate and dual-gate PNBT SOI-FETs.



Single-gate



Dual-gate

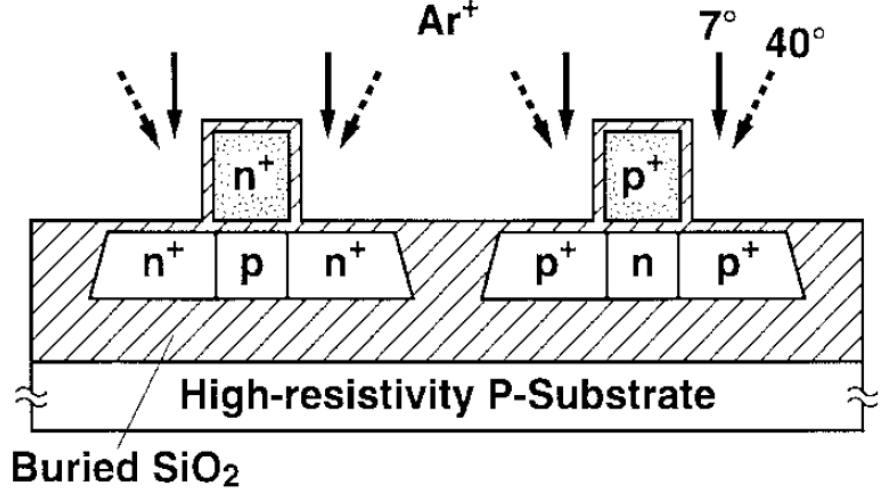


T. Ohno, et al., IEEE T-ED, May 1998.  
NTT

Ar-ion implantation

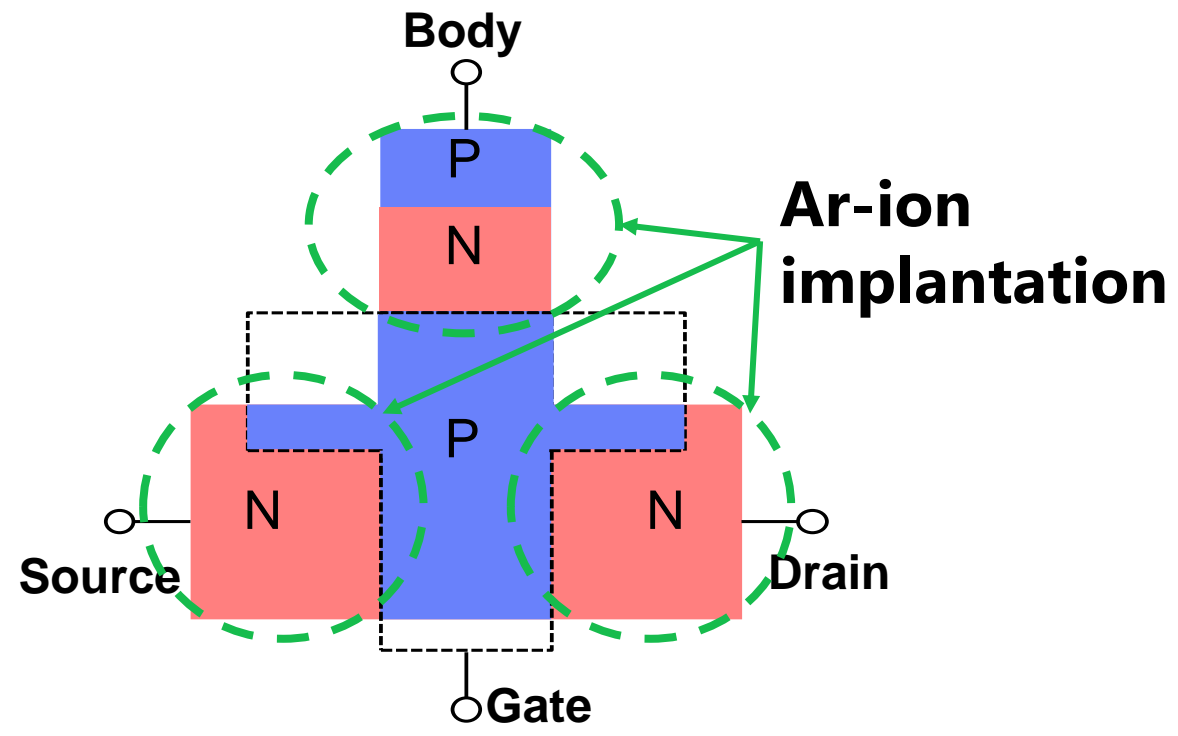
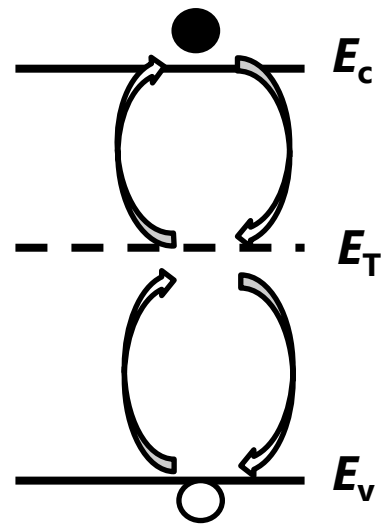
# Arイオン注入の効果

To suppress floating body effect



T. Ohno, et al., *IEEE T-ED*, May 1998.  
NTT

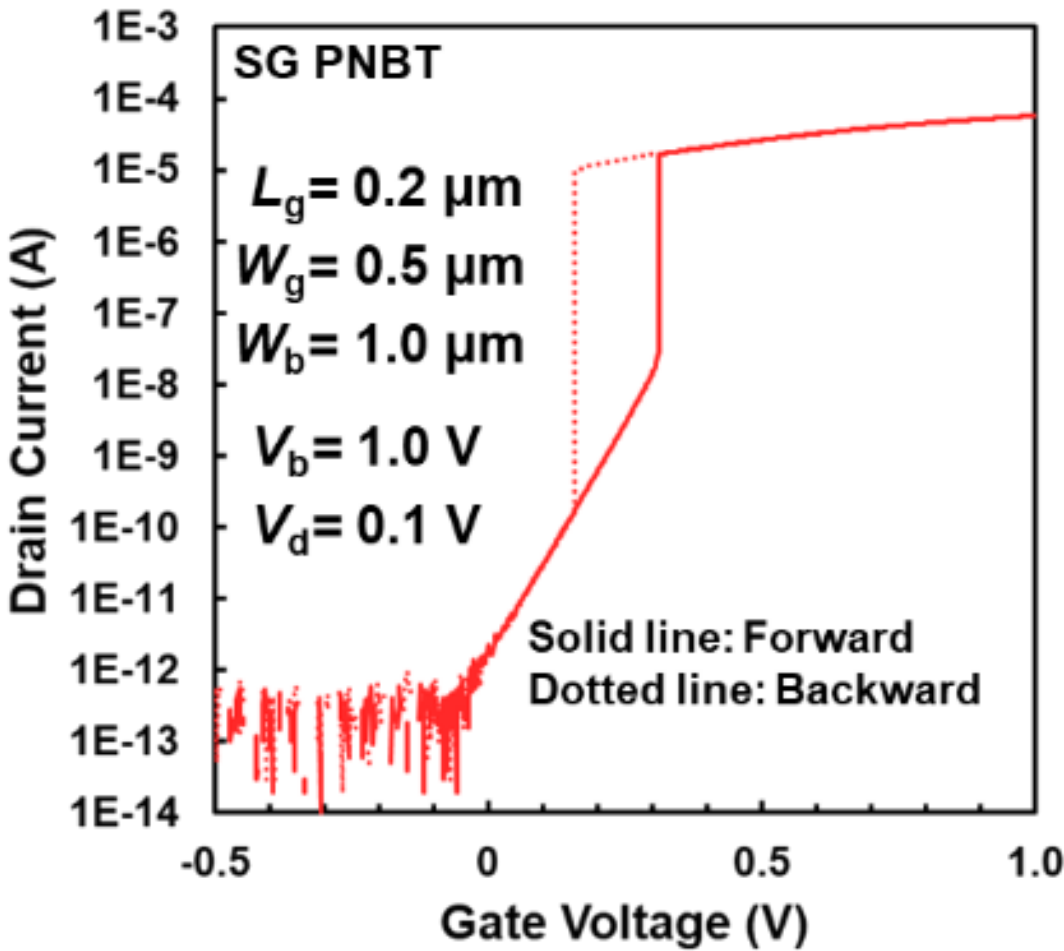
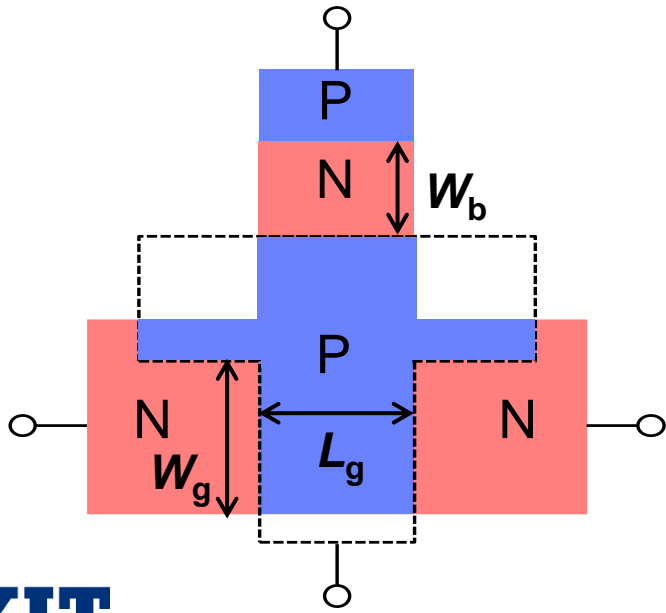
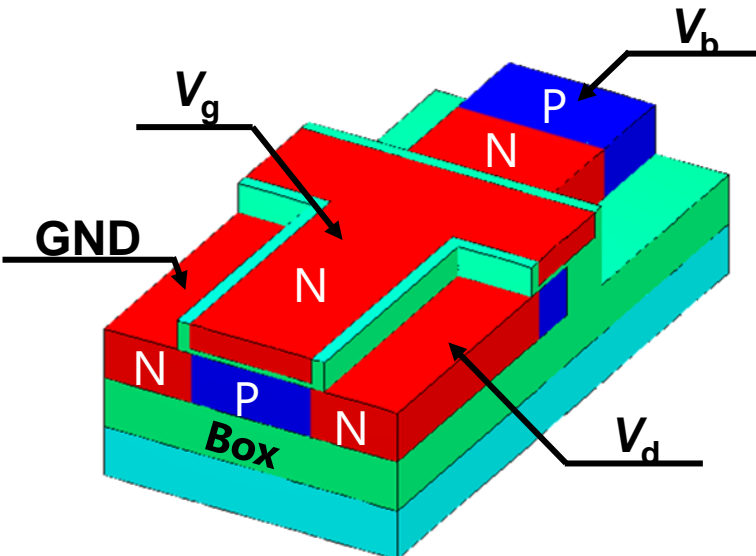
**Ar-ion implantation creates recombination centers, which act as lifetime killers.**



**Ar-ions were implanted after gate formation to reduce hysteresis.**  
(Ar-ions were not implanted to gate region)



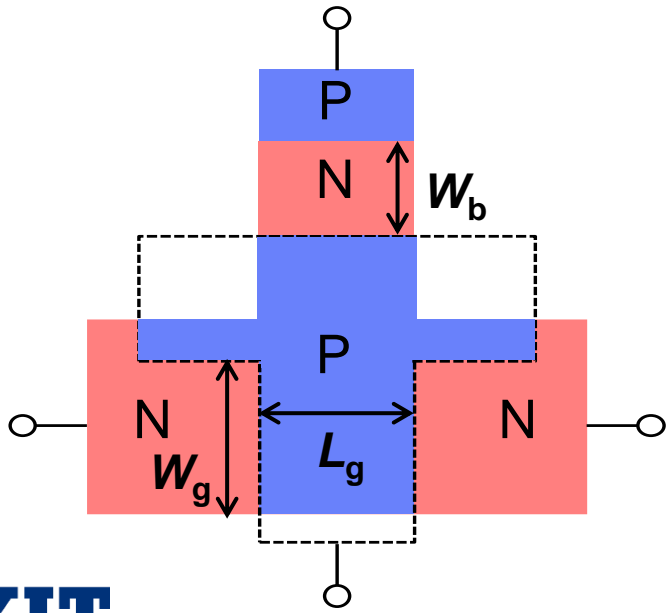
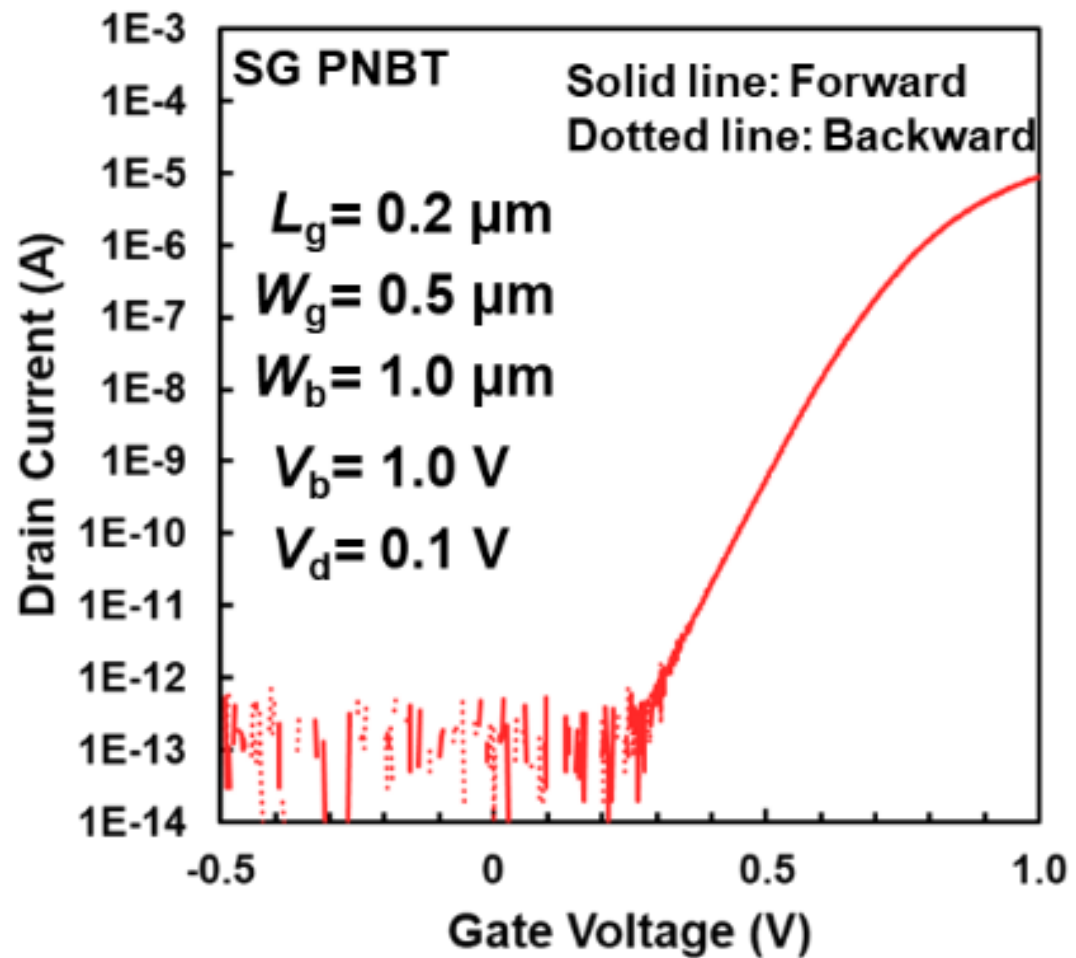
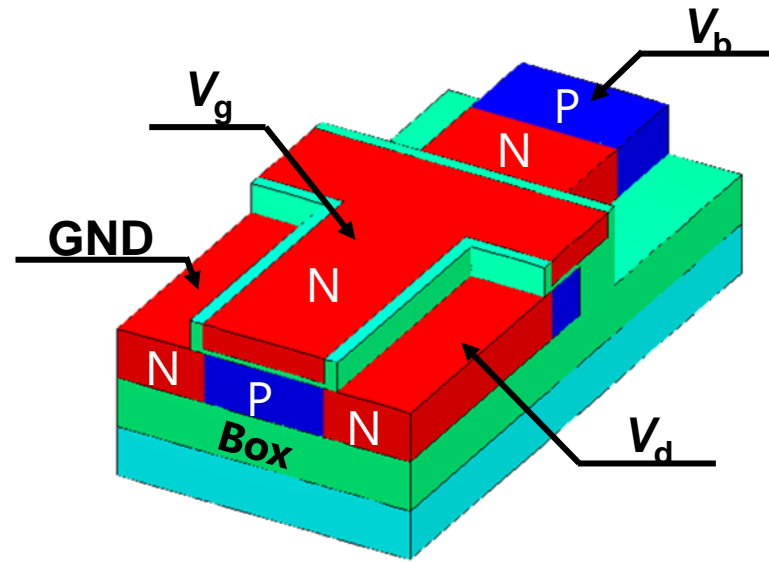
# Single-gate PNBT SOI-FET | no dose



**Steep SS and hysteresis occur.**

# Single-gate PNBT SOI-FET | with dose

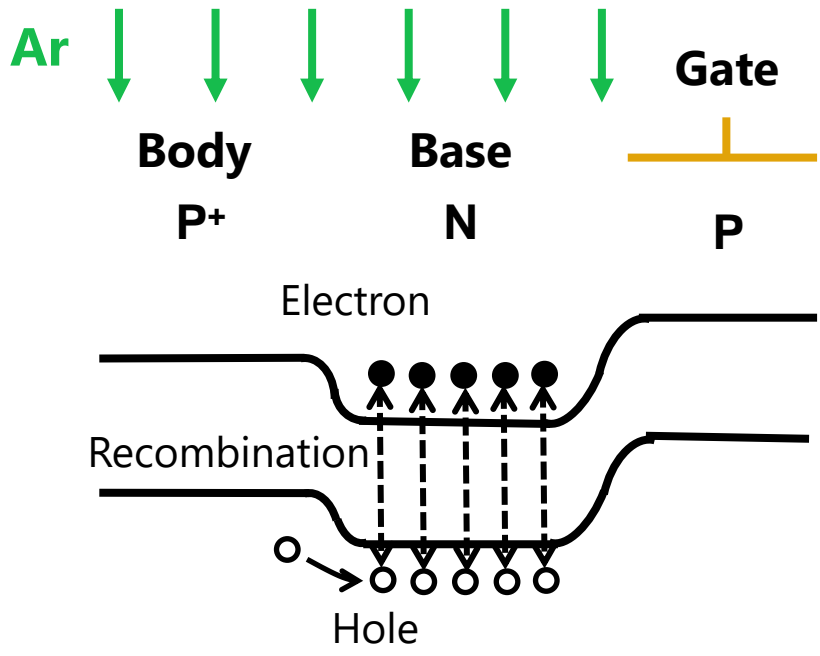
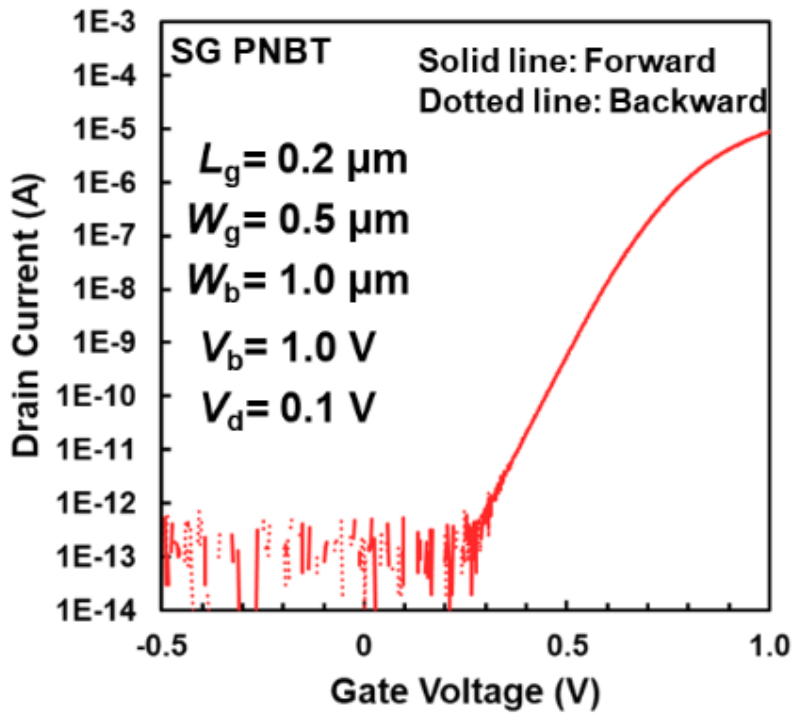
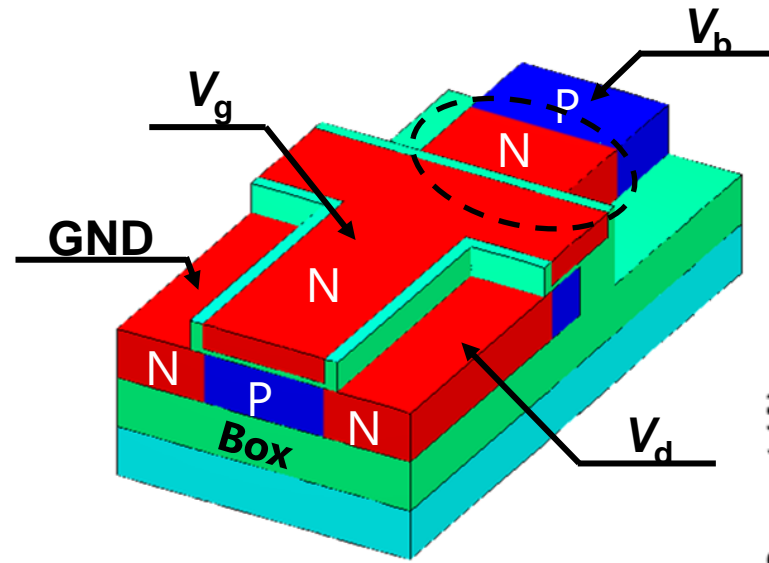
R. Ito *et al.*, IIT 2024.



**Hysteresis disappears but, steep SS also disappears.**

# Single-gate PNBT SOI-FET | with dose

R. Ito *et al.*, IIT 2024.



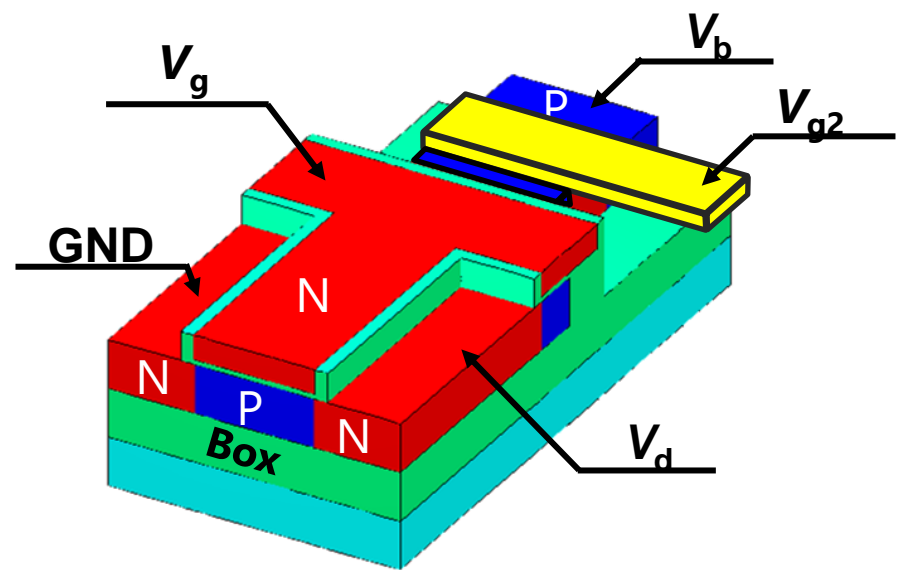
**High Ar dose induces high recombination rate.**



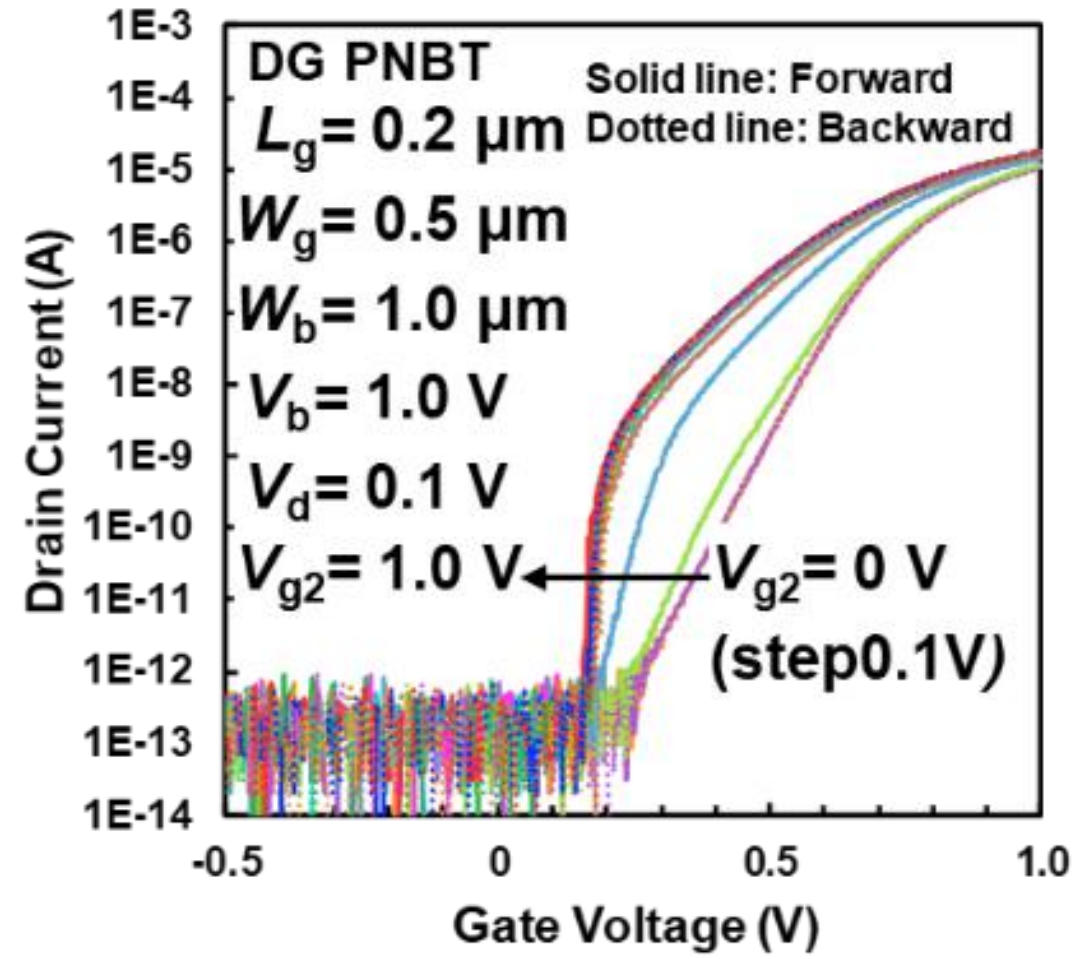
**carrier injection efficiency decreases, and steep SS disappears.**

# Dual-gate PNBT SOI-FET | with dose

R. Ito *et al.*, IIT 2024.



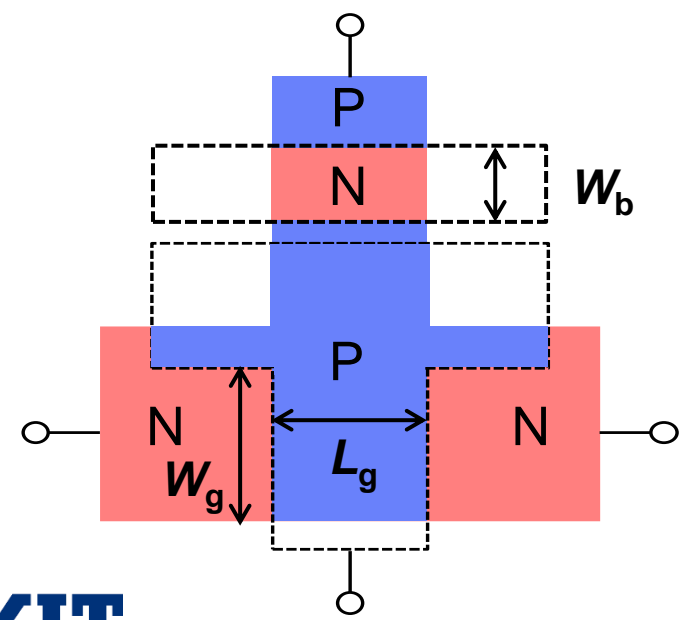
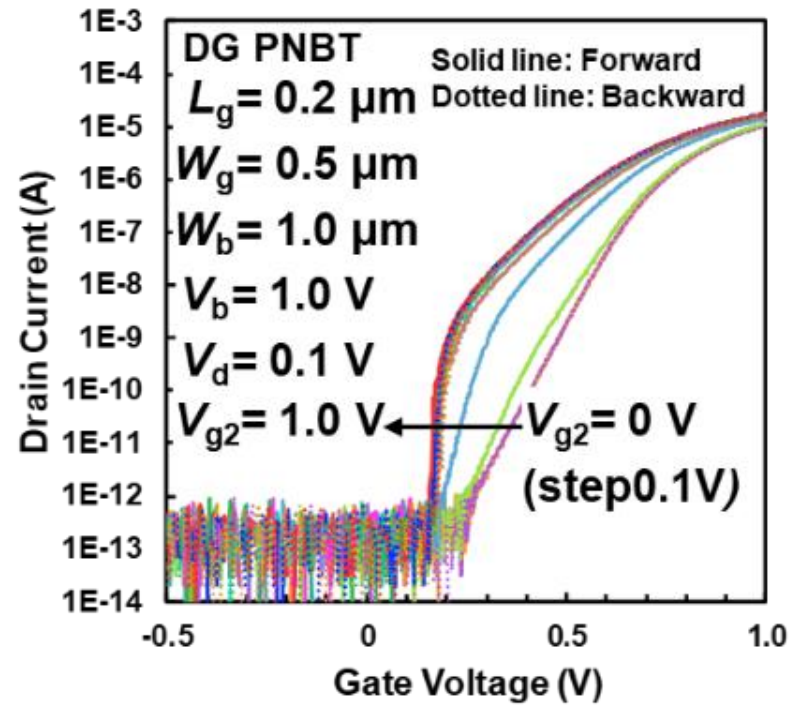
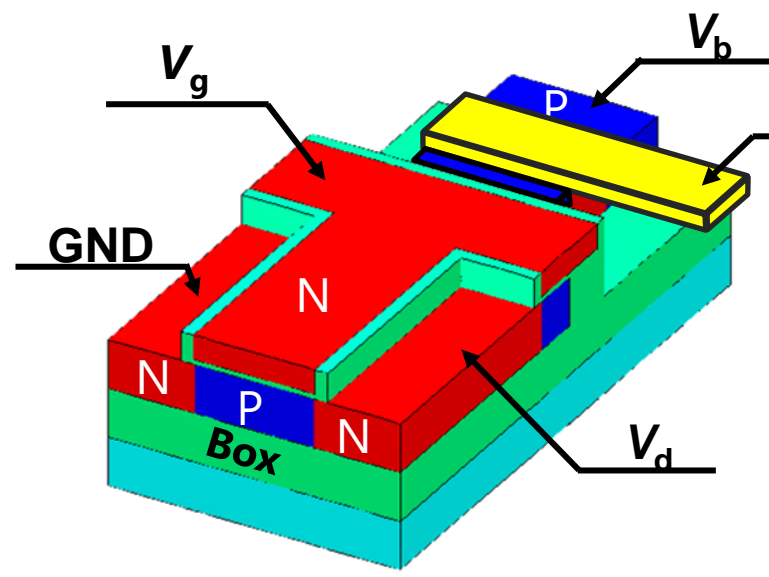
DG PNBT SOI-FET has an additional 2<sup>nd</sup> gate which can control potential of N-body region.



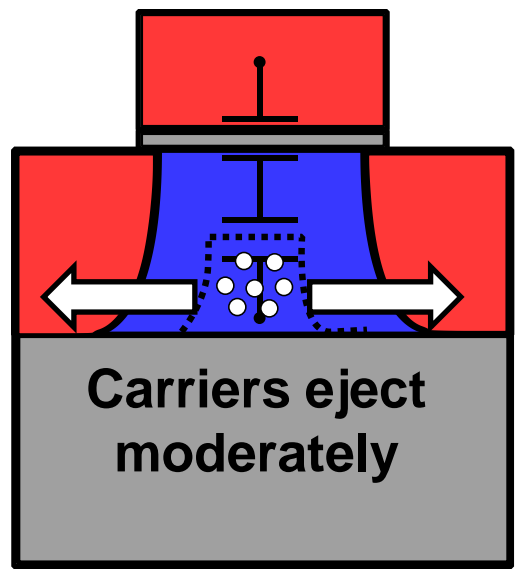
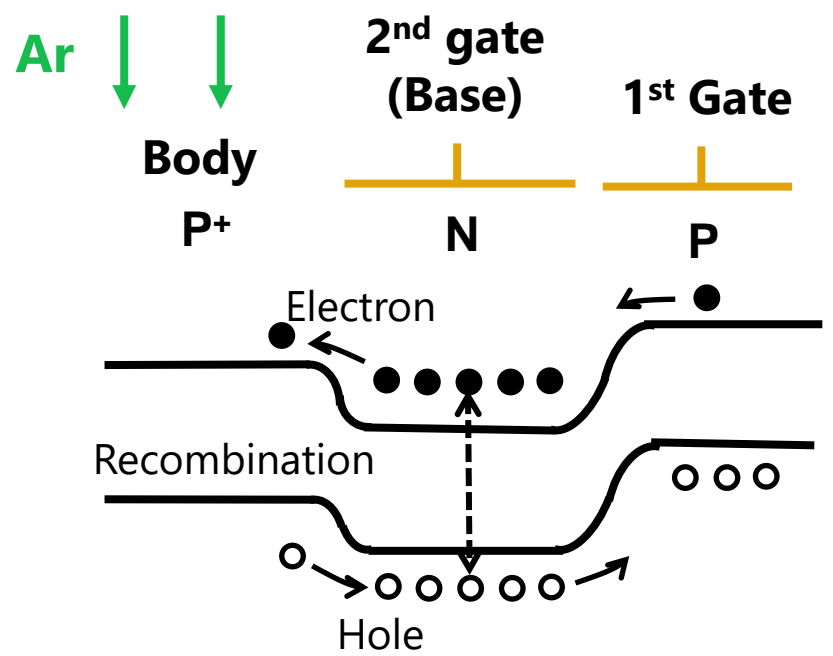
**Steep SS occur without hysteresis !**

# Dual-gate PNBT SOI-FET | with dose

R. Ito *et al.*, IIT 2024.

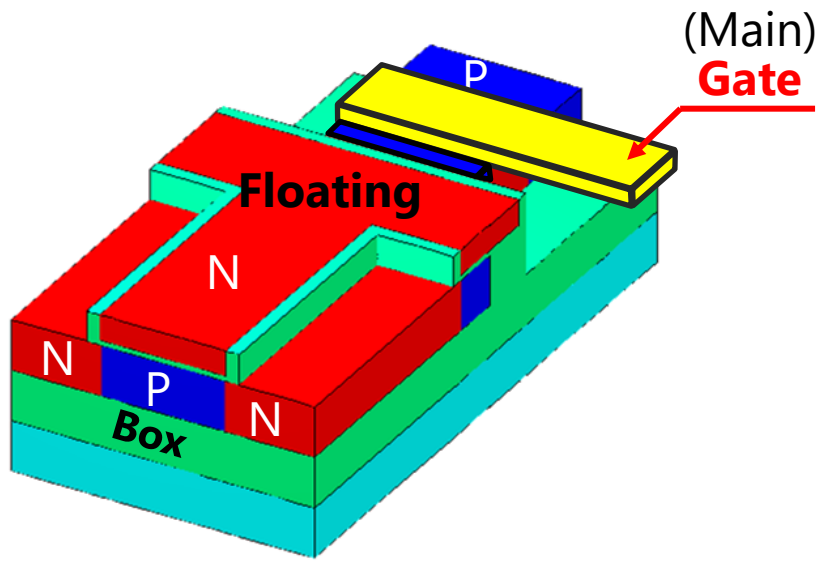


**DG PNBT SOI-FET achieves moderately positive feedback.**

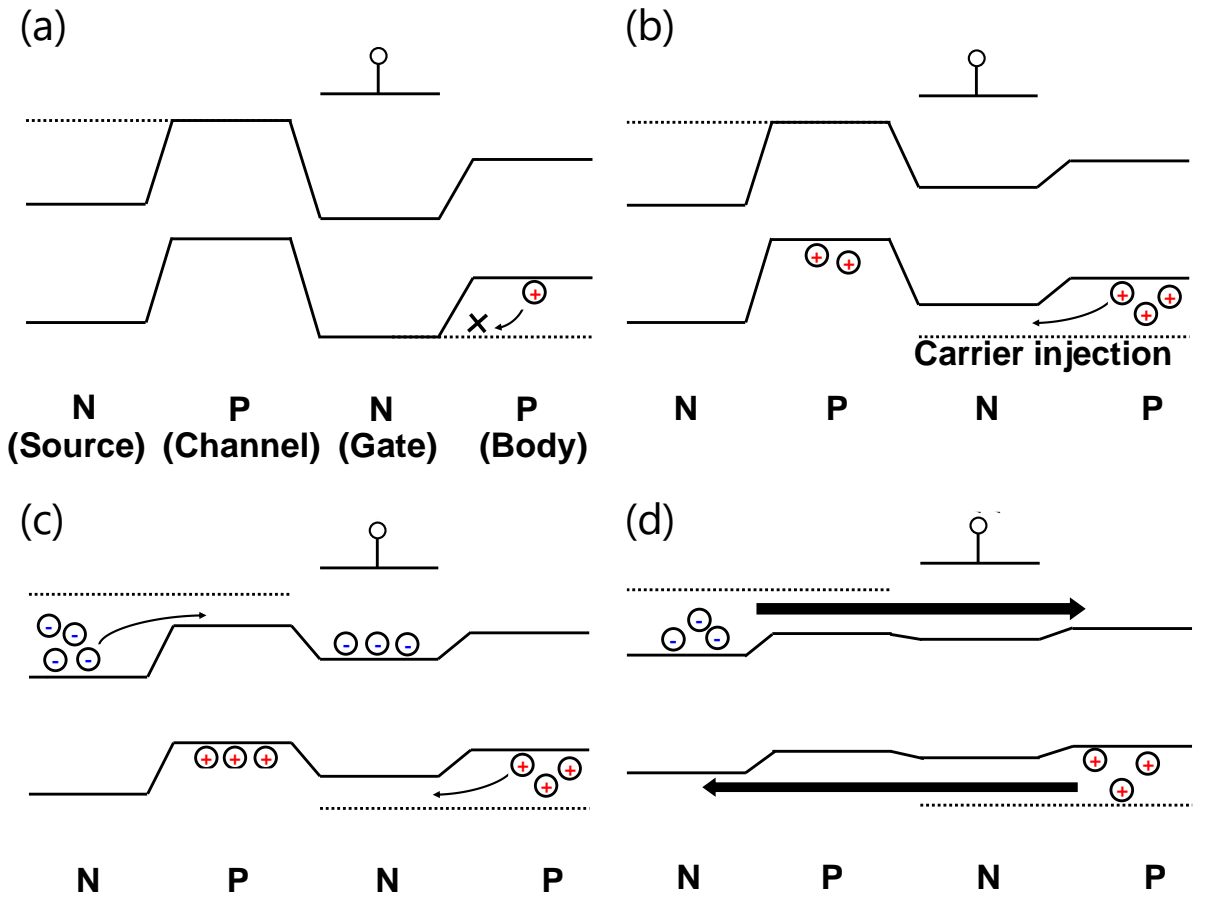


# Gate-Controlled Carrier-Injection SOI-Tr

H. Yonezaki et al., EDTM 2024



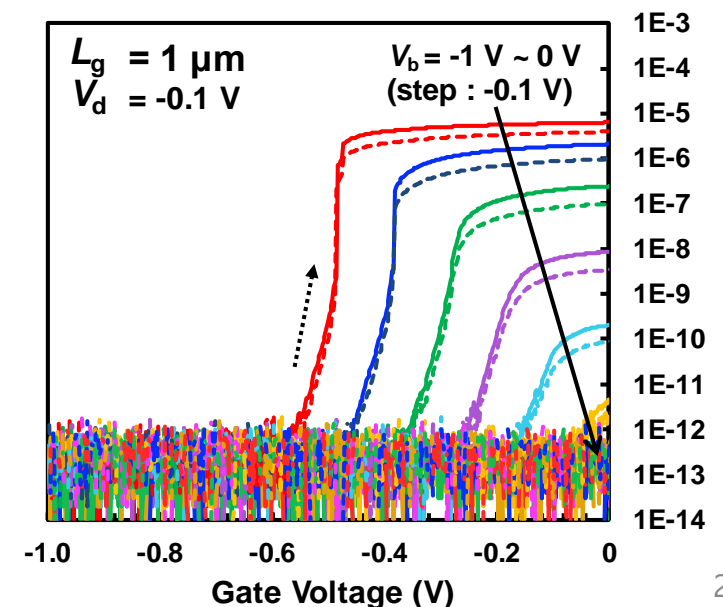
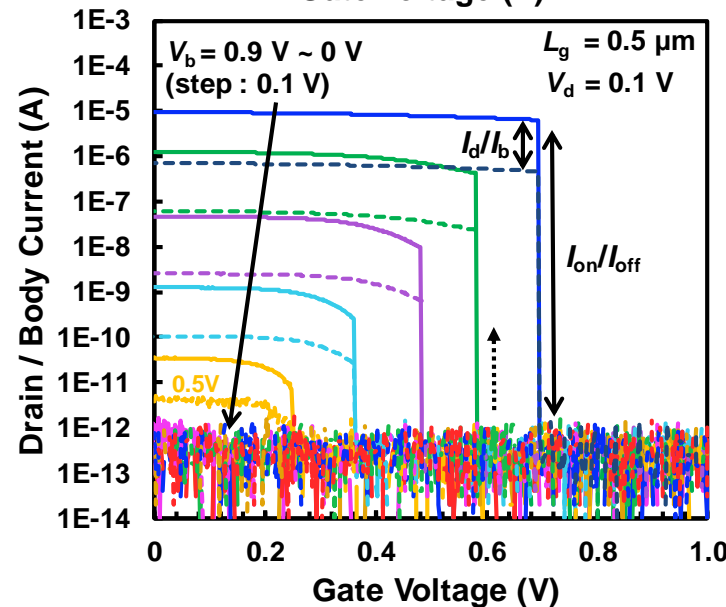
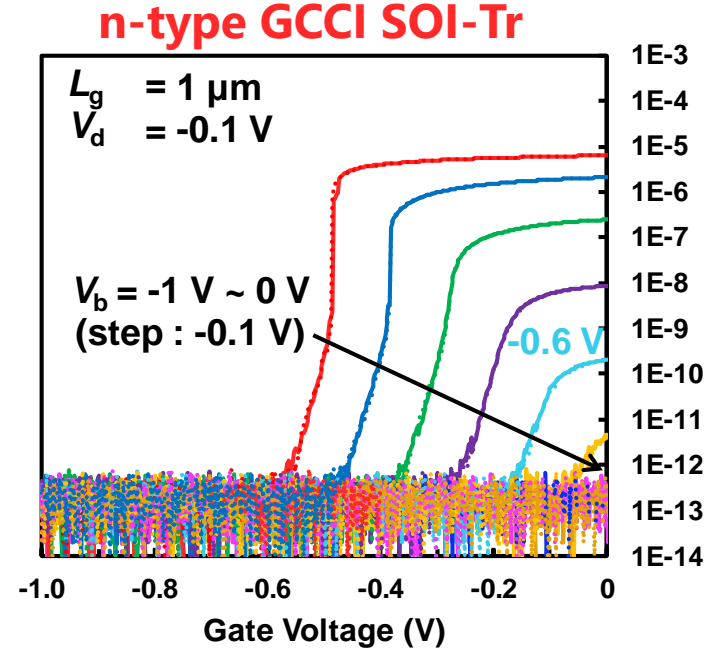
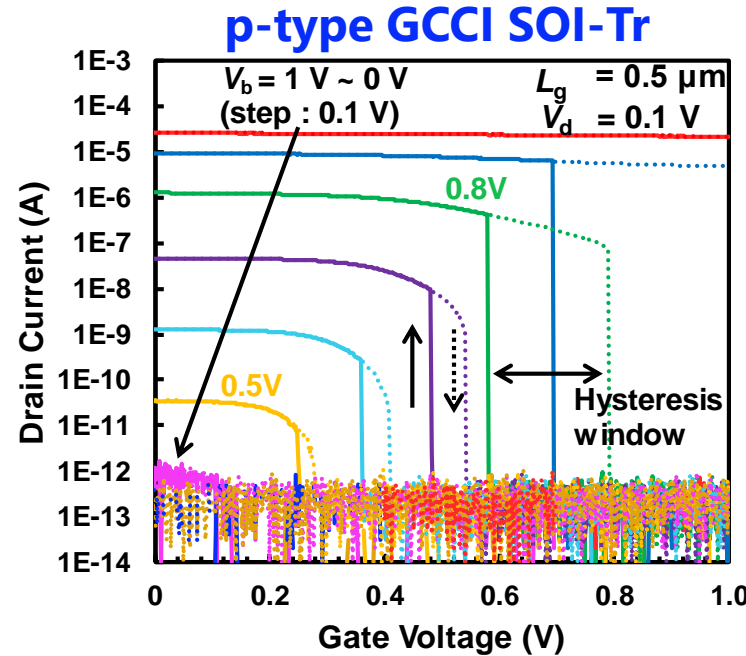
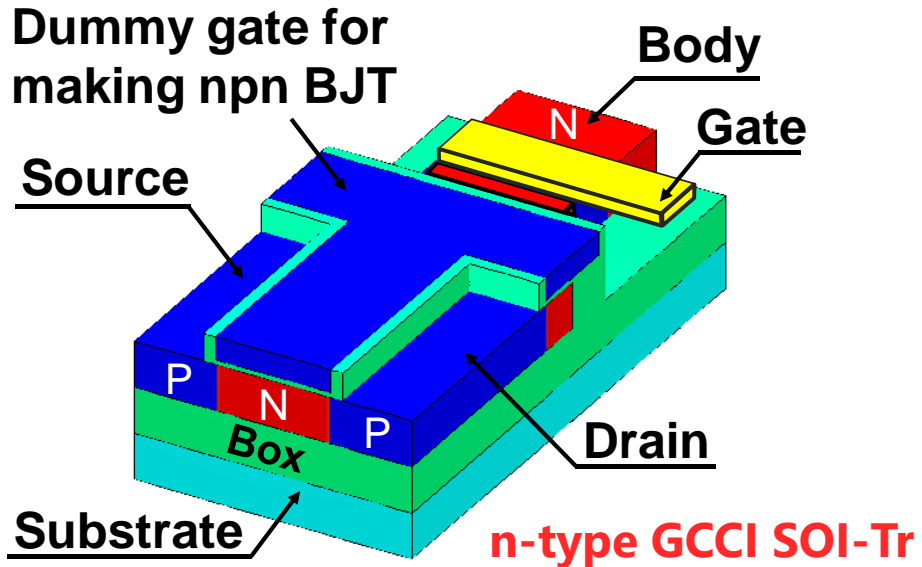
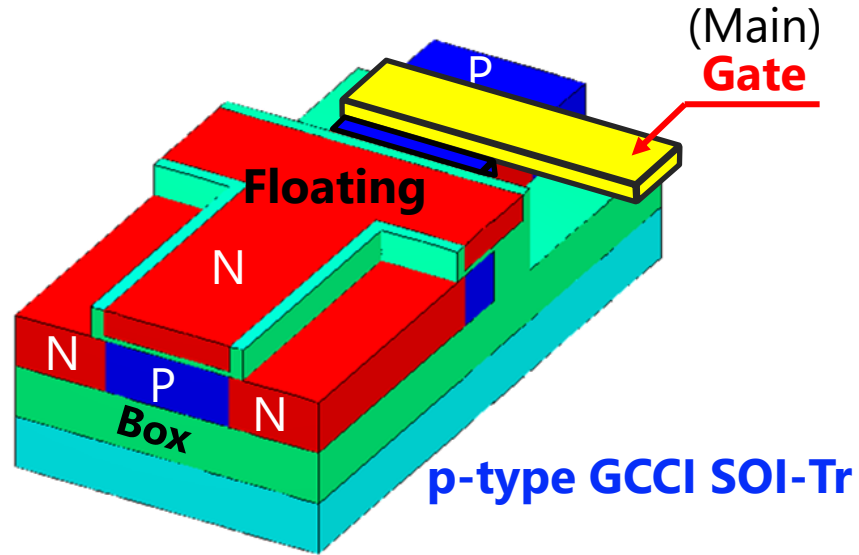
Gate-Controlled Carrier-Injection SOI-Tr (GCCI SOI-Tr)



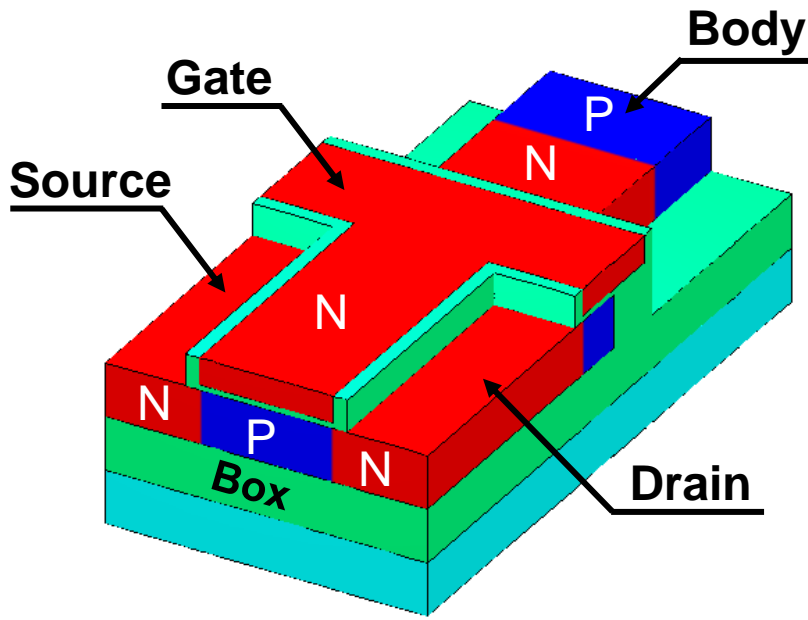
想定動作メカニズム

DG PNBT SOI-FETの2nd GateをメインのGateとして扱う (1st GateはFloating)  
 使用端子数減、制御の単純化が見込める

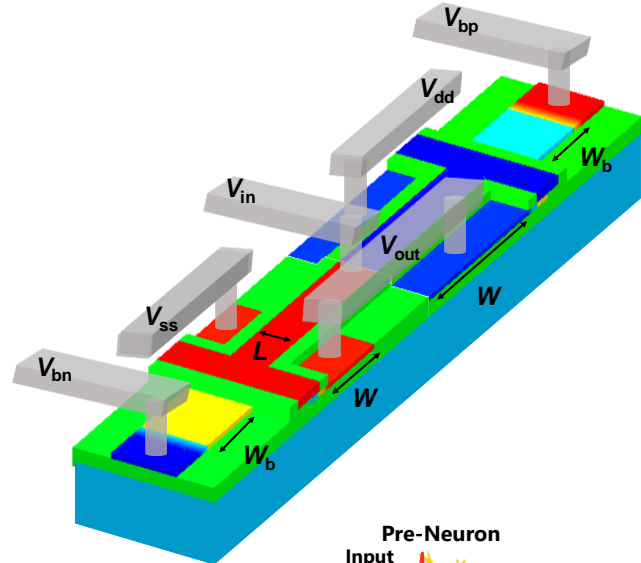




# PNBT SOI-FETを用いた極低消費電力アプリケーション例

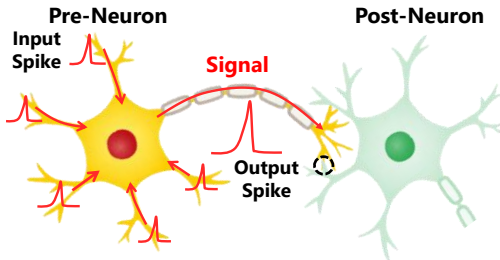


**PNBT SOI-FET**



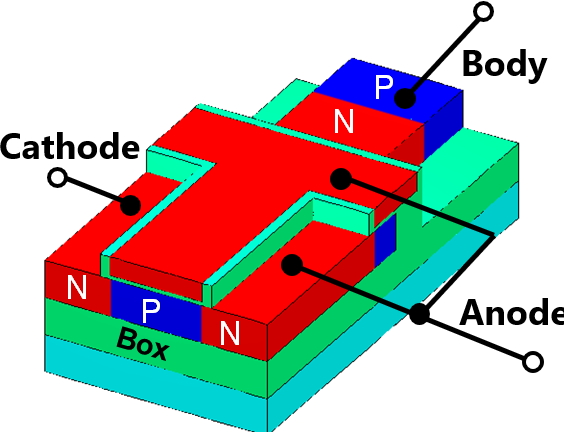
**Steep switching CMOS inverter**

S. Ishiguro, et al., *VLSI-TSA*, 2021.



**Neuromorphic device**

T. Sasaki, et al., *EDTM*, 2022.



**Steep switching diode for RF energy harvesting**

T. Mori, et al., *IEEE J-EDS*, 2018.

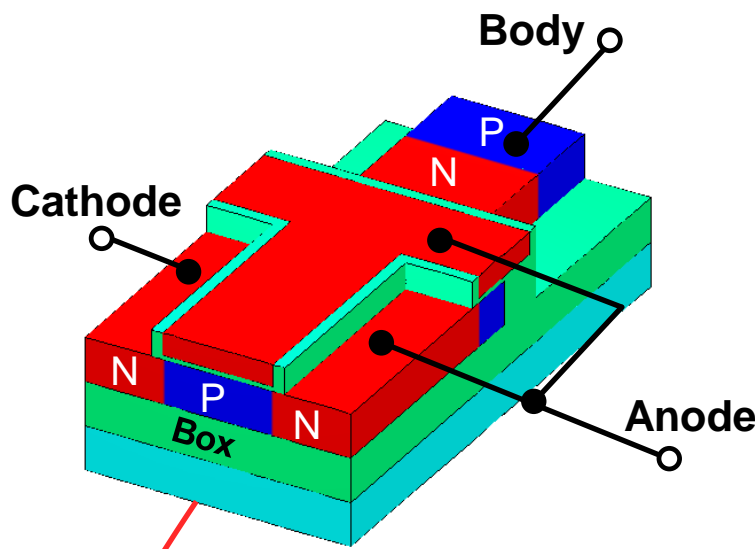
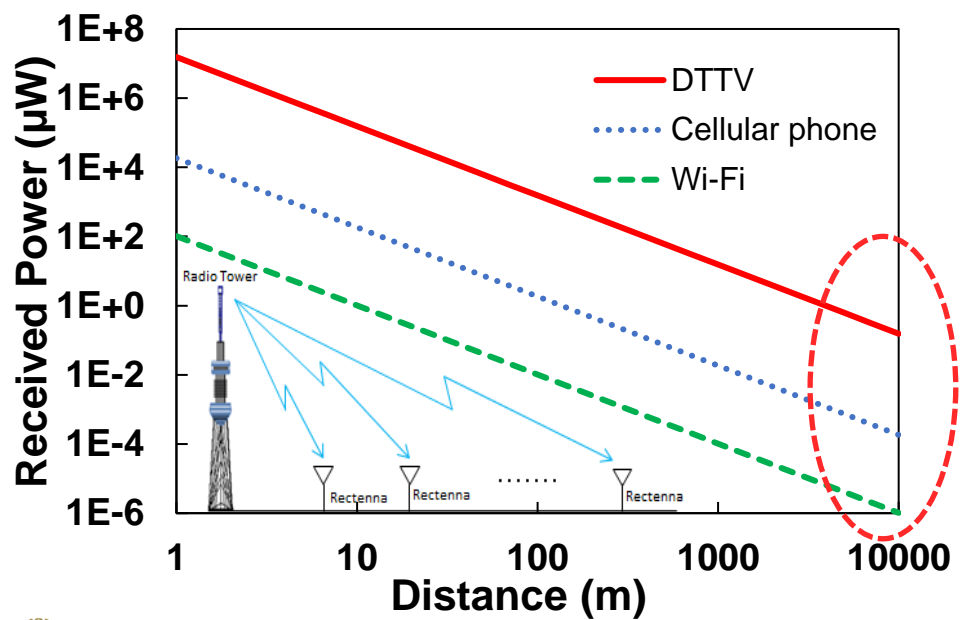


# 環境発電用整流デバイスの研究

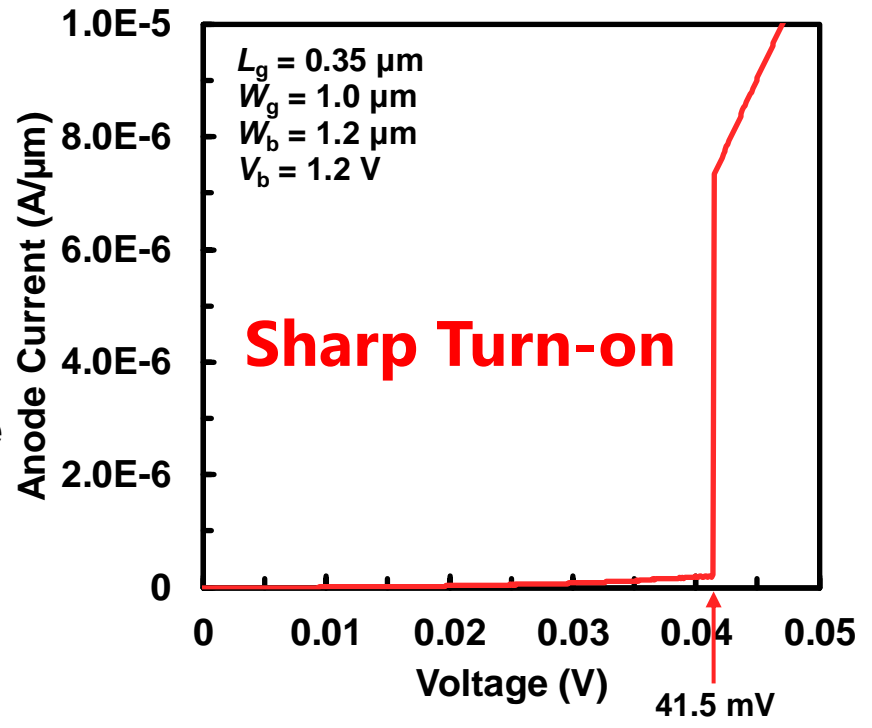
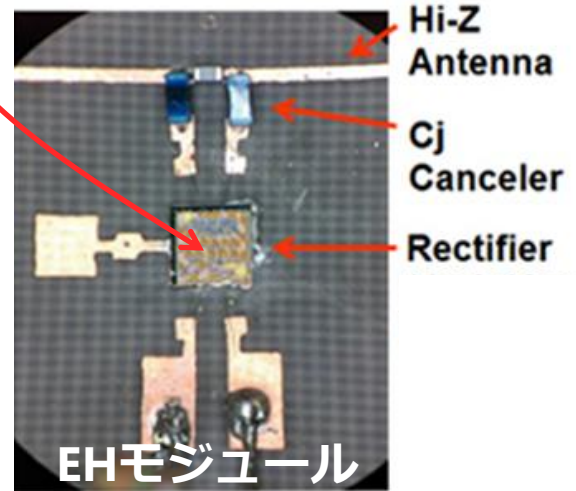
環境発電 (Energy Harvesting : EH)  
 環境中にある熱や振動などの  
 エネルギーを集めて発電する



環境中に飛んでいる電波に着目！  
 しかし・・・  
 →微小な電波を整流する素子が必要



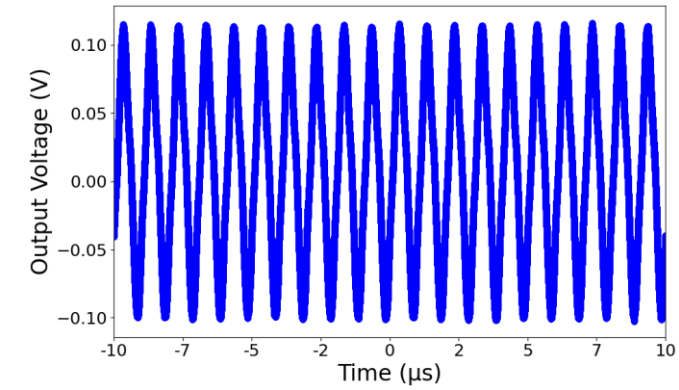
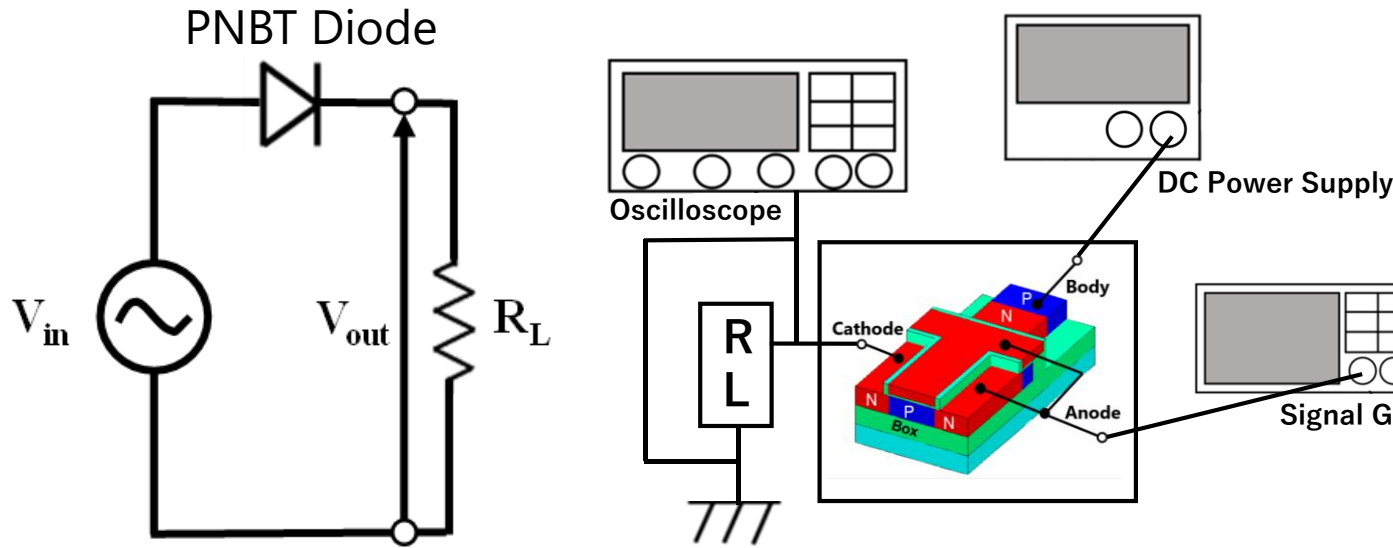
PNBT Diode



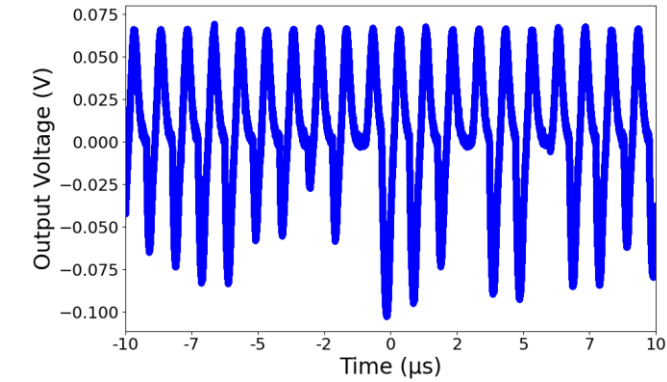
PNBT Diodeを使用した整流回路  
 によって微小な電波からの発電を  
 目指す

# PNBT Diodeを用いた半波整流実験

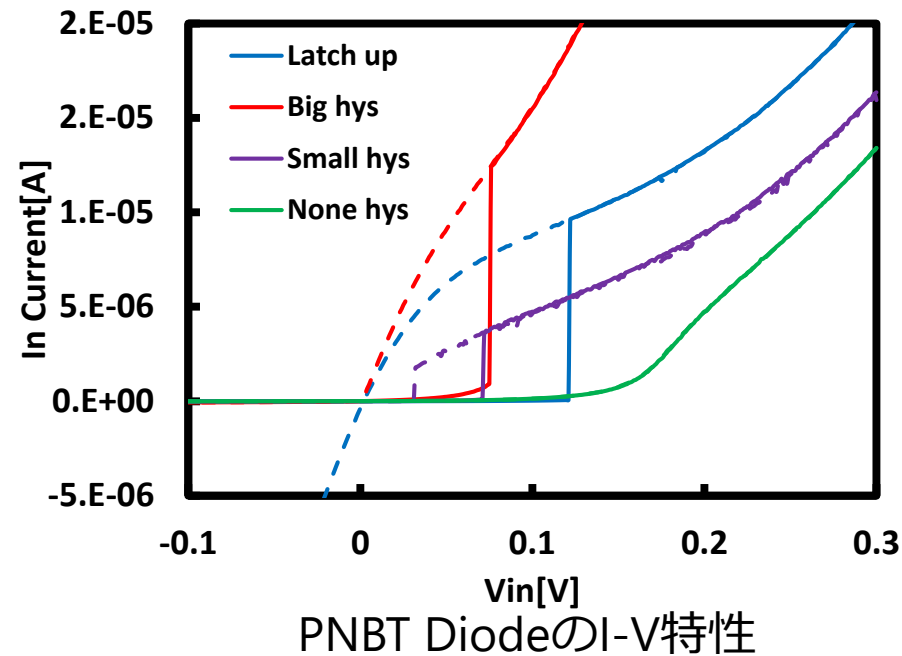
H. Matsushita *et al.*, TJMW 2024.



Latch upデバイス使用時の出力電圧



Small Hys. デバイス使用時の出力電圧



PNBT DiodeのI-V特性

Gate下やBase部にキャリアが残っていることで逆方向バイアス時にも（過渡的には）完全なOFF状態にならない？

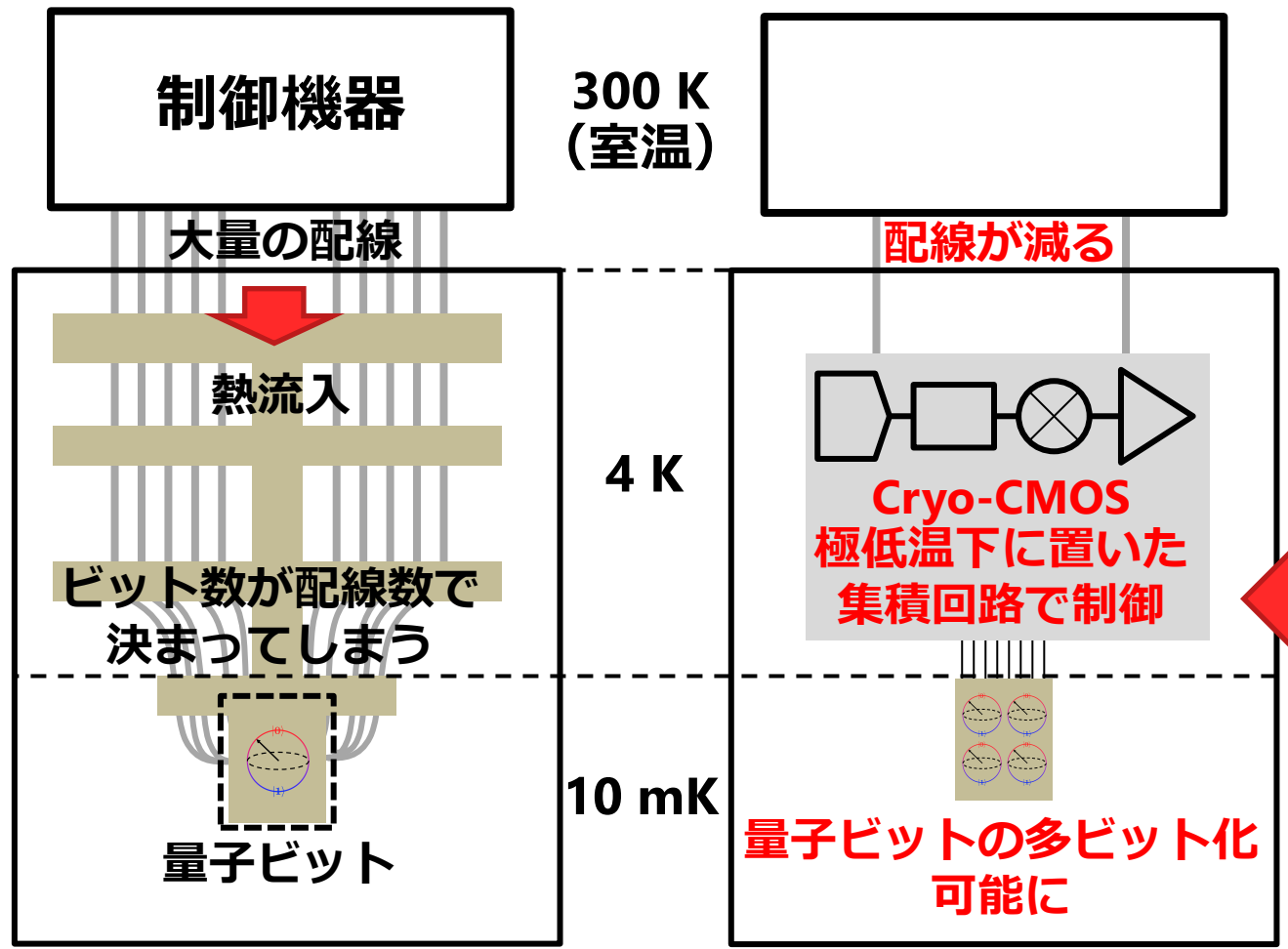
→Arイオン注入で制御できないか？

# Cryo-CMOS

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# 極低温CMOS回路用デバイスの研究

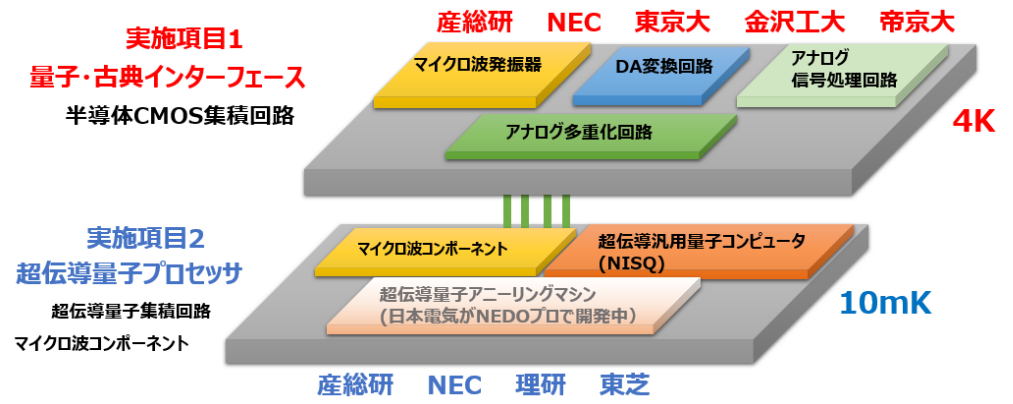
現在の計算機の性能を凌駕すると期待される  
 <量子コンピュータ>



現行の量子コンピュータ

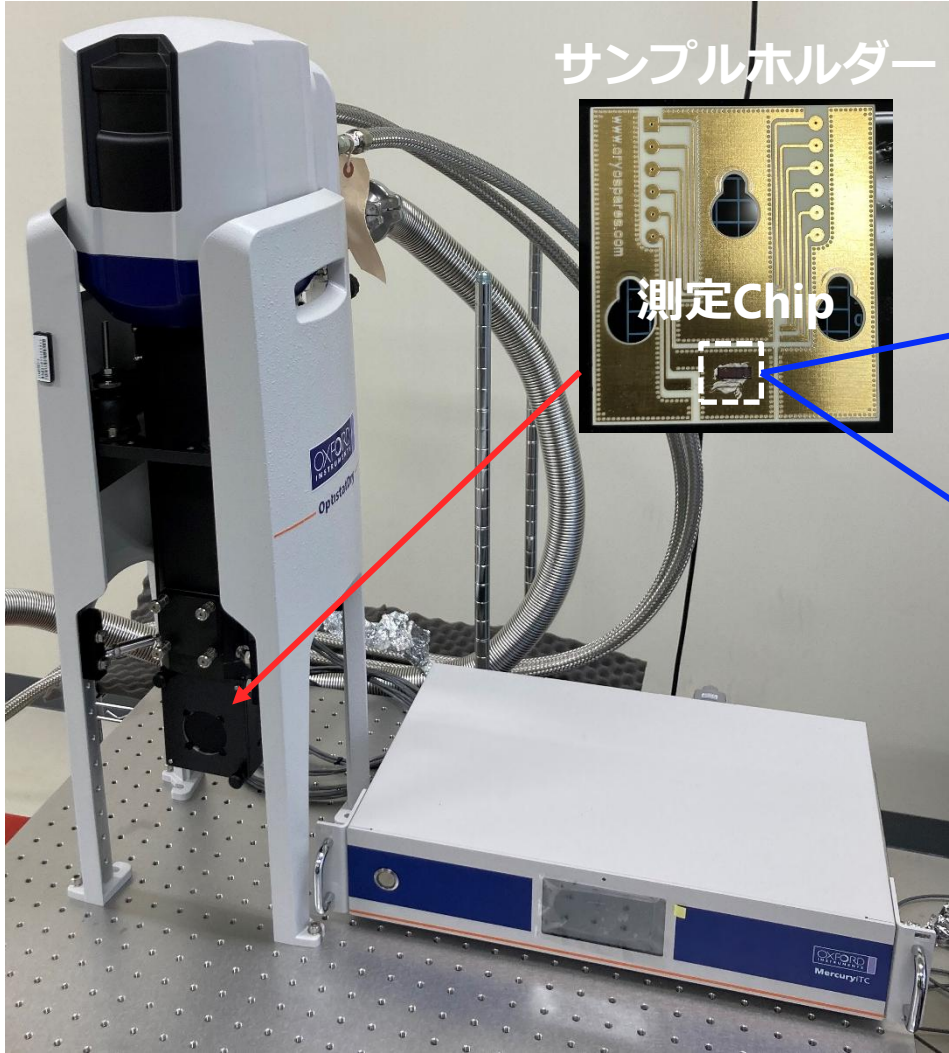
Cryo-CMOSによる制御

## NEDO 委託で実施



極低温下で低消費電力な  
 デバイスが必要

# 極低温CMOS回路用デバイスの研究

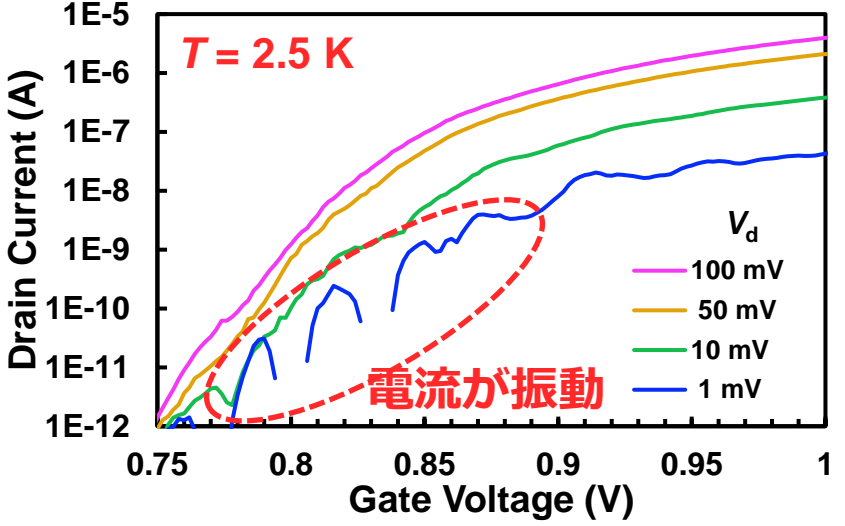
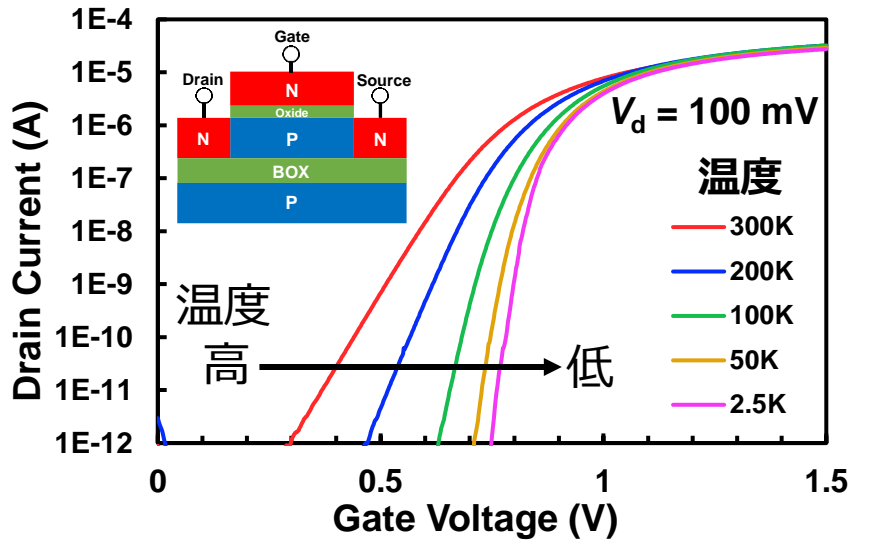


サンプルホルダー

測定Chip

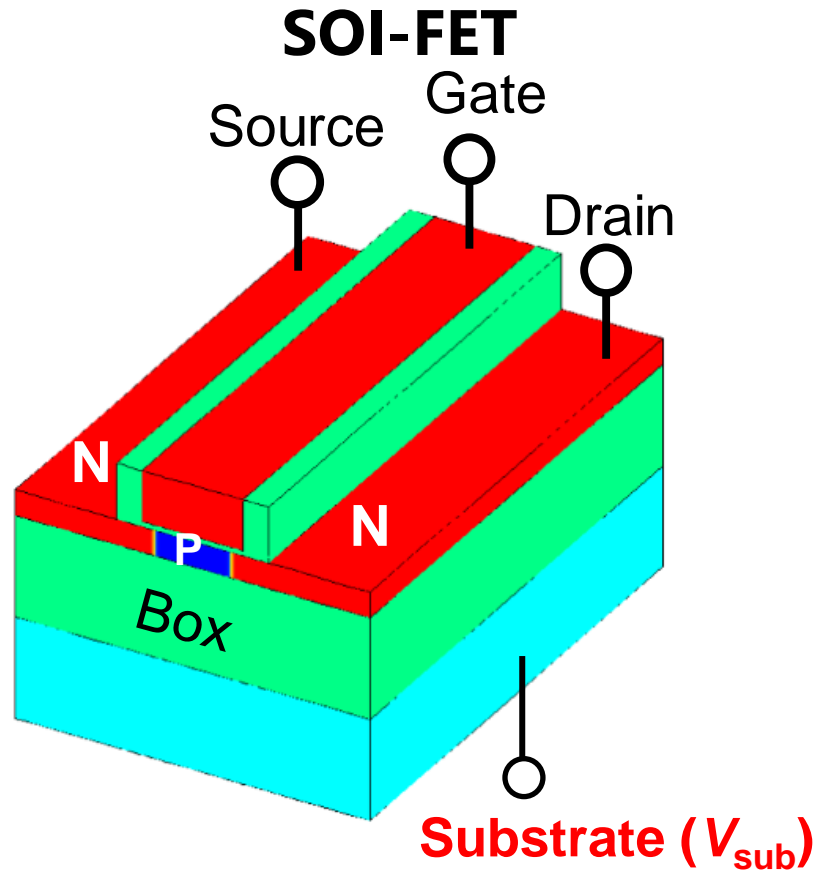
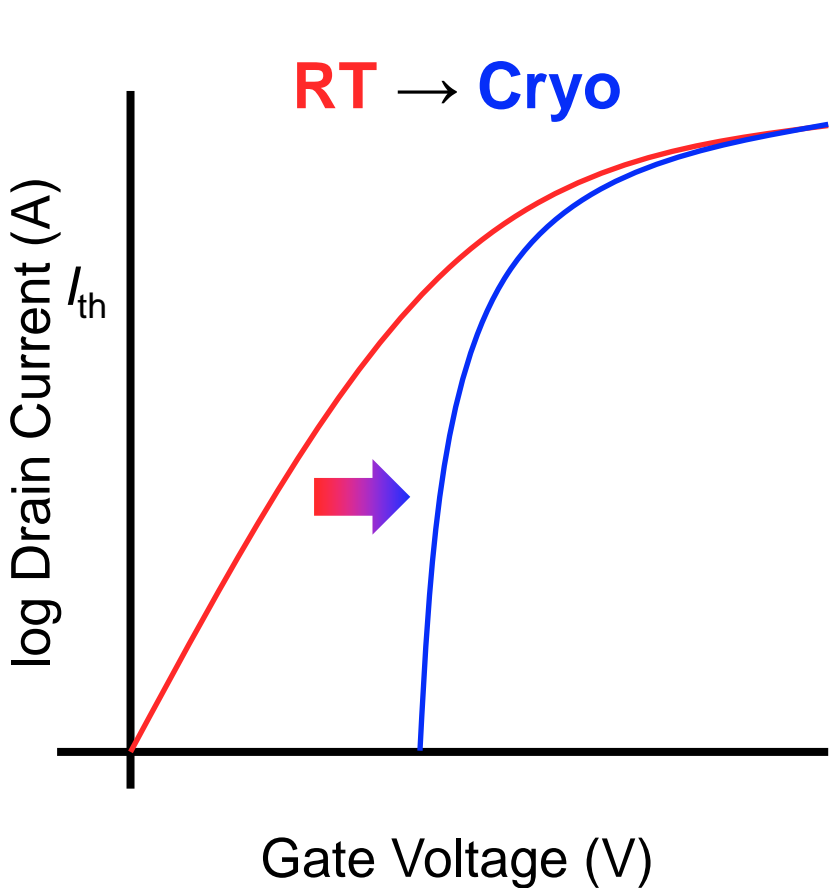
クライオスタット (産総研からの貸与)

~2 Kの極低温下で測定が可能



極低温下MOSFETの動作メカニズム解明が必要

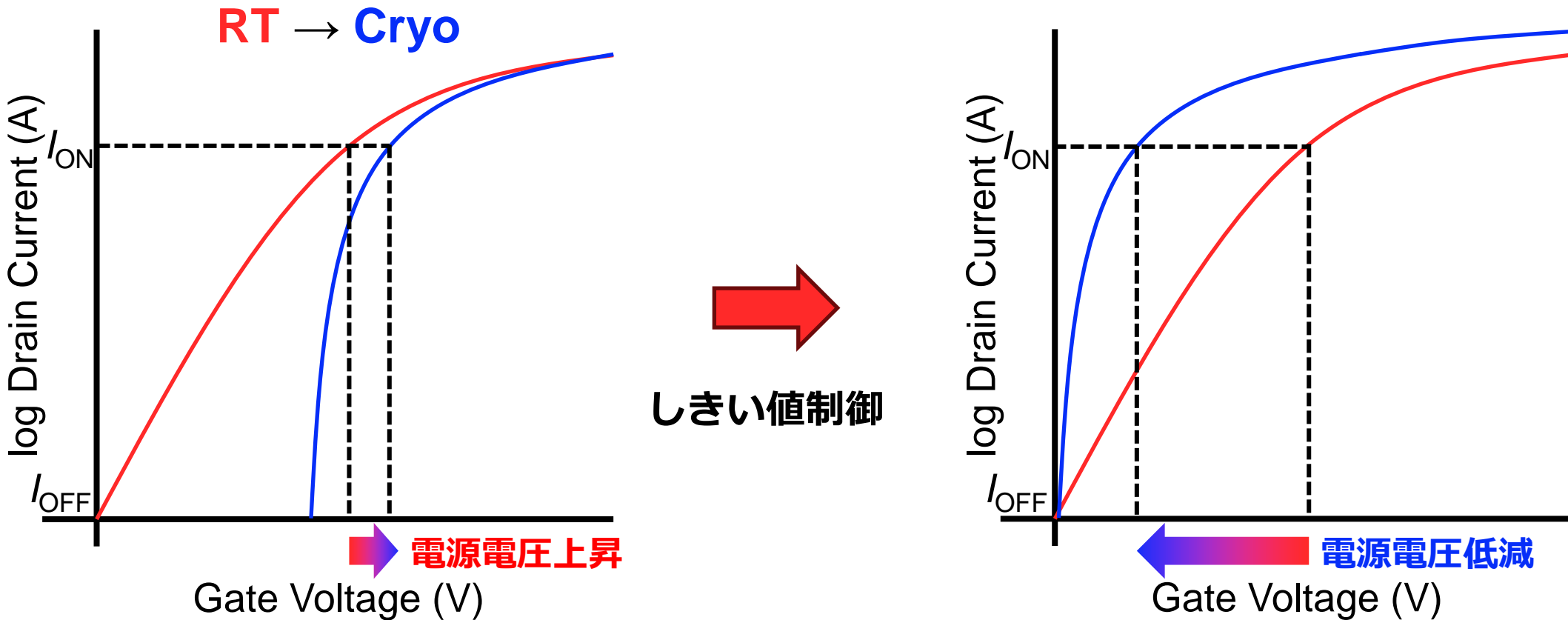
# SOI-FETへの期待 | 極低温下におけるしきい値の制御



極低温環境下では電気的特性が変動

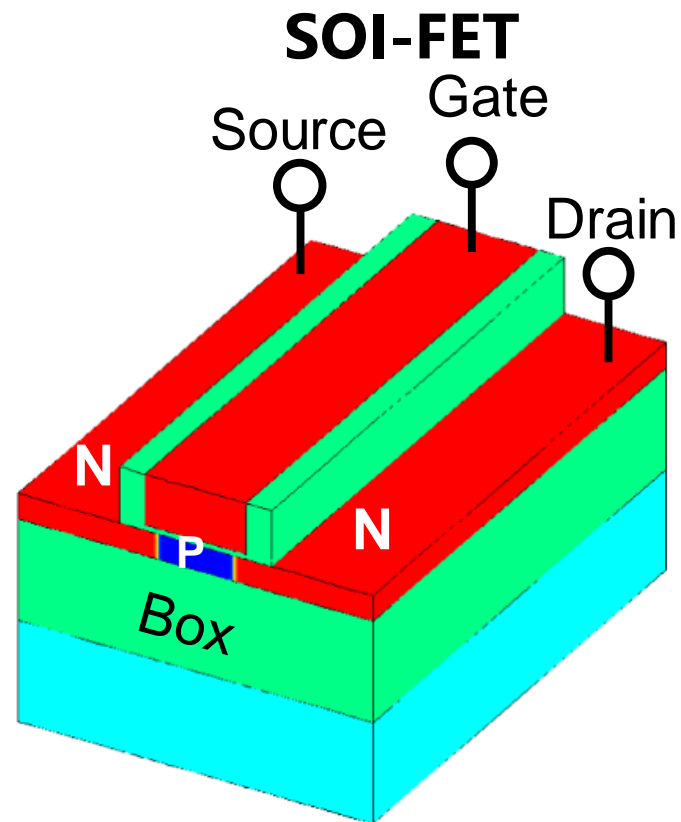
SOI-FETの基板バイアスによって制御

# SOI-FETへの期待 | 極低温下におけるしきい値の制御



基板バイアスによりしきい値を制御することで電源電圧を低減し低消費電力化する

# SOI-FETの懸念点



- ・ **フローティングボディ効果の影響**

基板が浮いている（フローティングボディ）ためキャリアの蓄積やそれに付随した履歴効果が起こる

- ・ **Si/Box側界面の影響**

Bulk MOSFETに対して埋め込み酸化膜(Box)側にも界面ができる

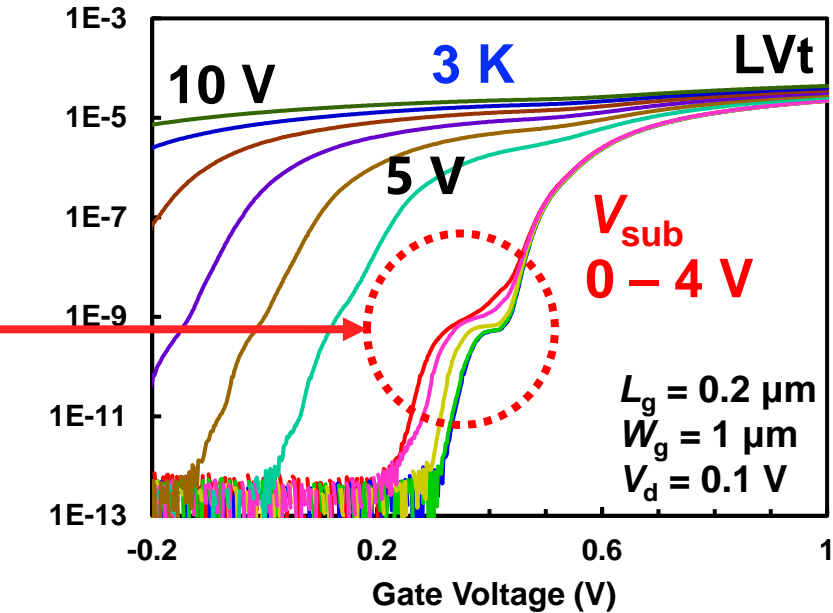
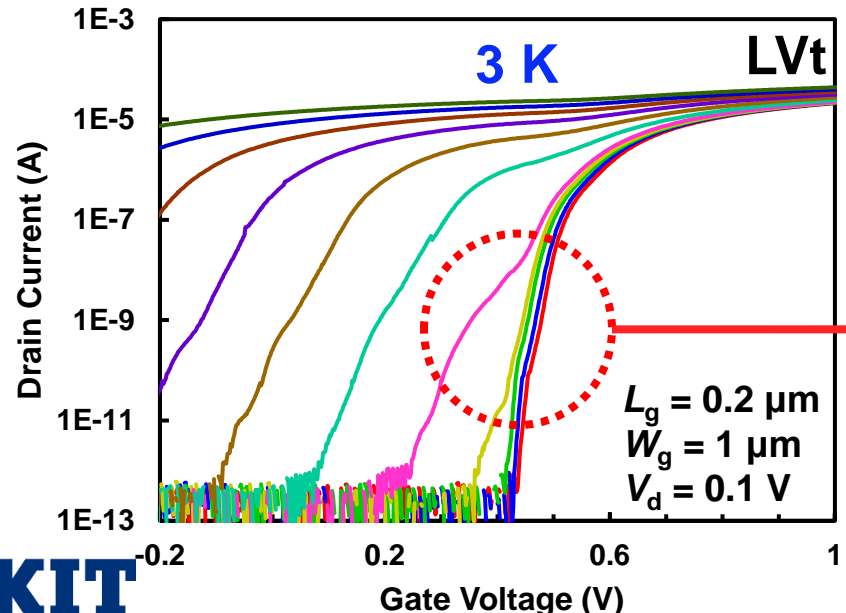
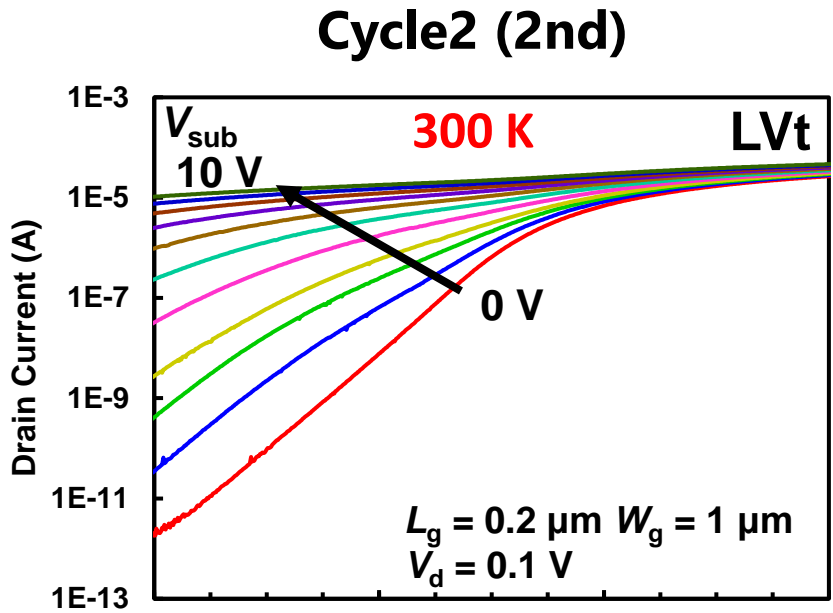
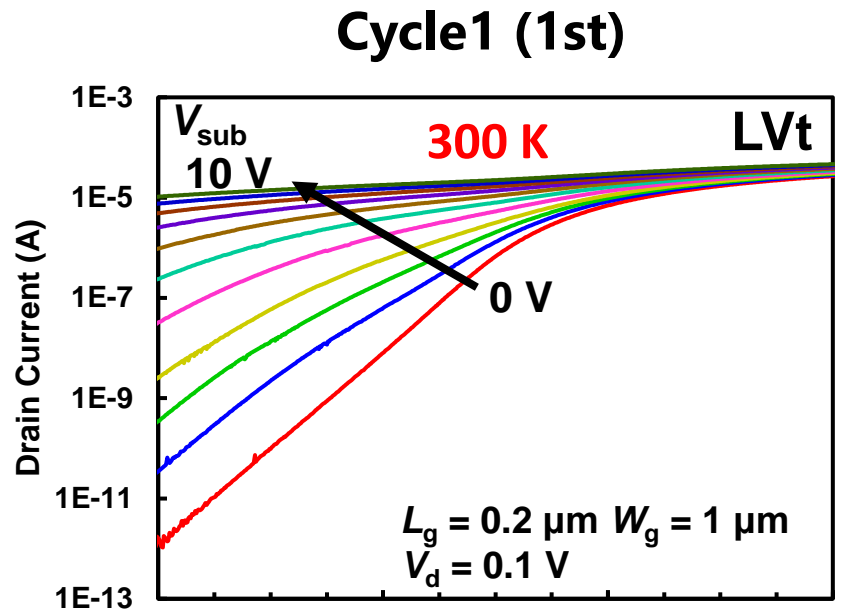
- ・ **熱の影響**

SOI-FETでは放熱がBoxによって妨げられるため自己加熱効果 (Self-Heating) の影響が大きくなる

上記の影響が**極低温下**ではどうなる？



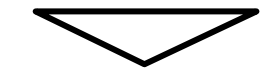
# 正の基板バイアス依存性 (履歴効果)



**< 300 K >**

**$V_{sub}$  0 - 10 V**  
**2cycles**

**Same results**



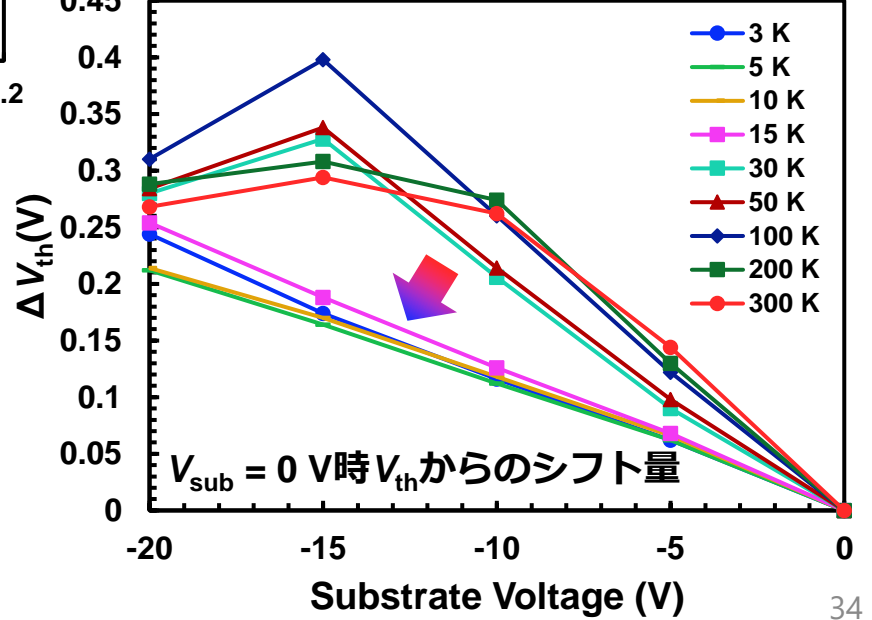
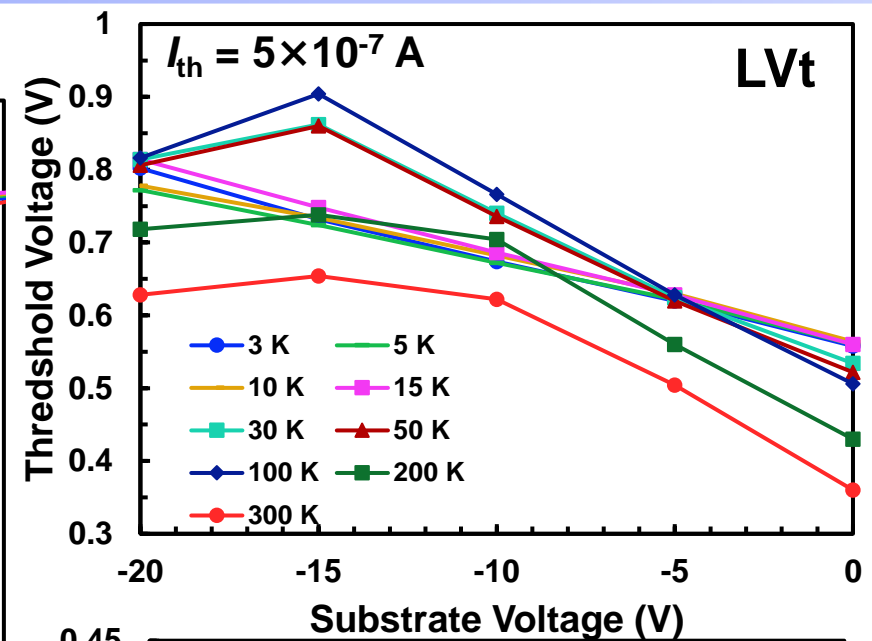
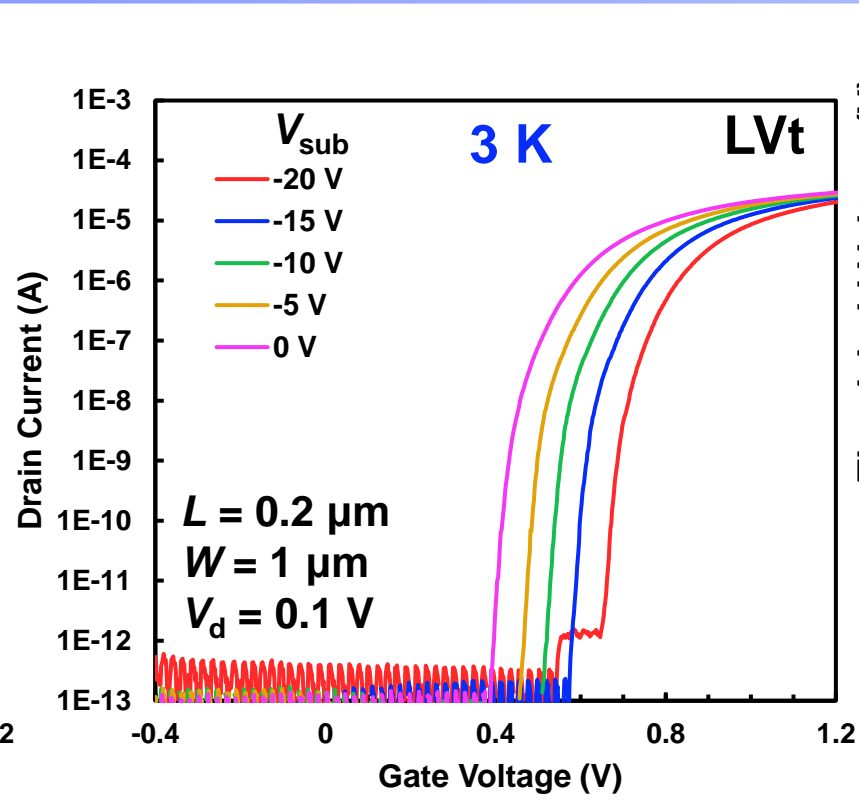
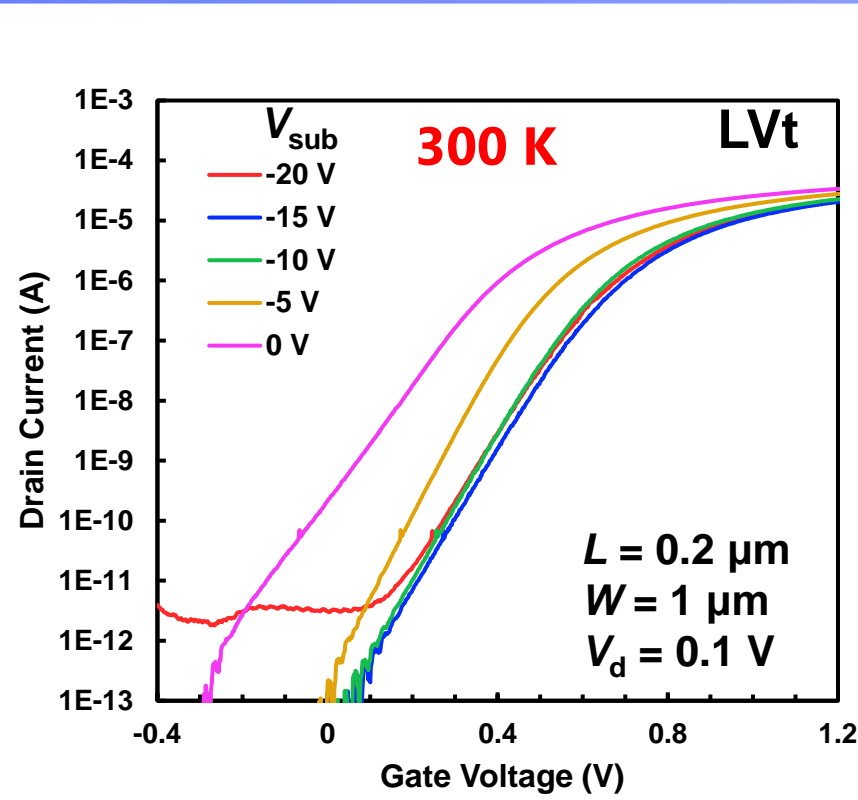
**< 3 K >**

**$V_{sub}$  0 - 10 V**  
**2cycles**

**Shift**  
**( at 2nd )**

極低温下でのみ働くトラップが影響？

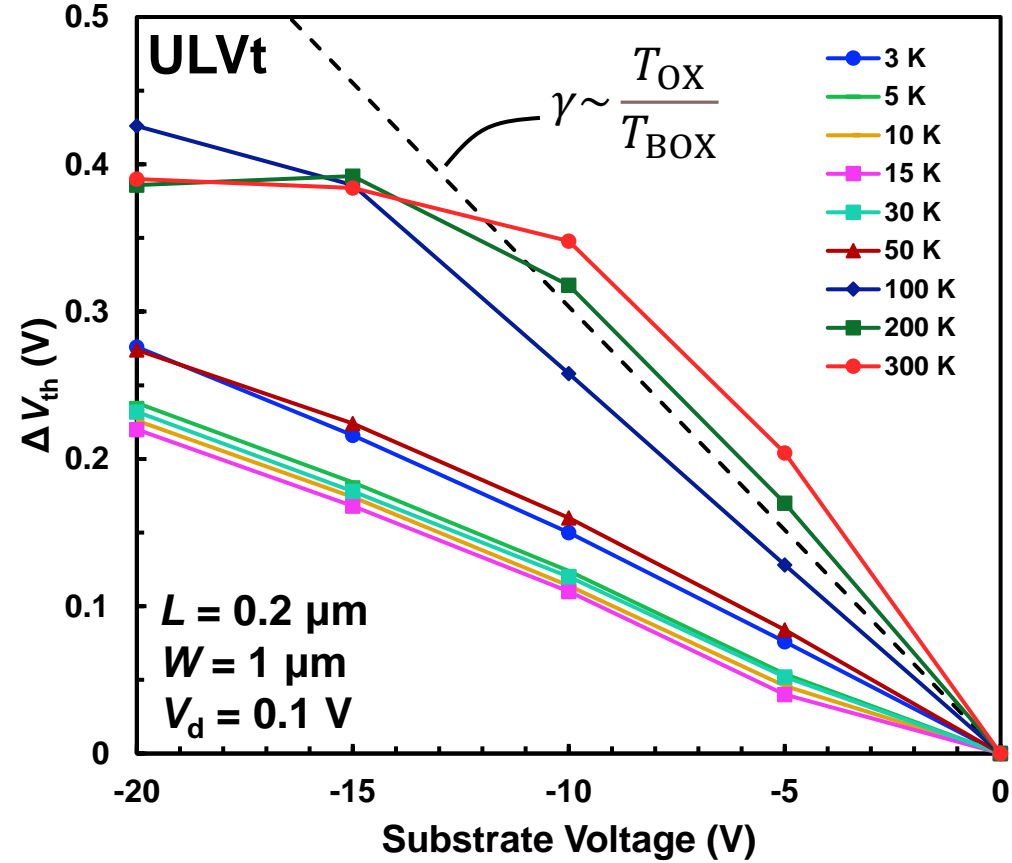
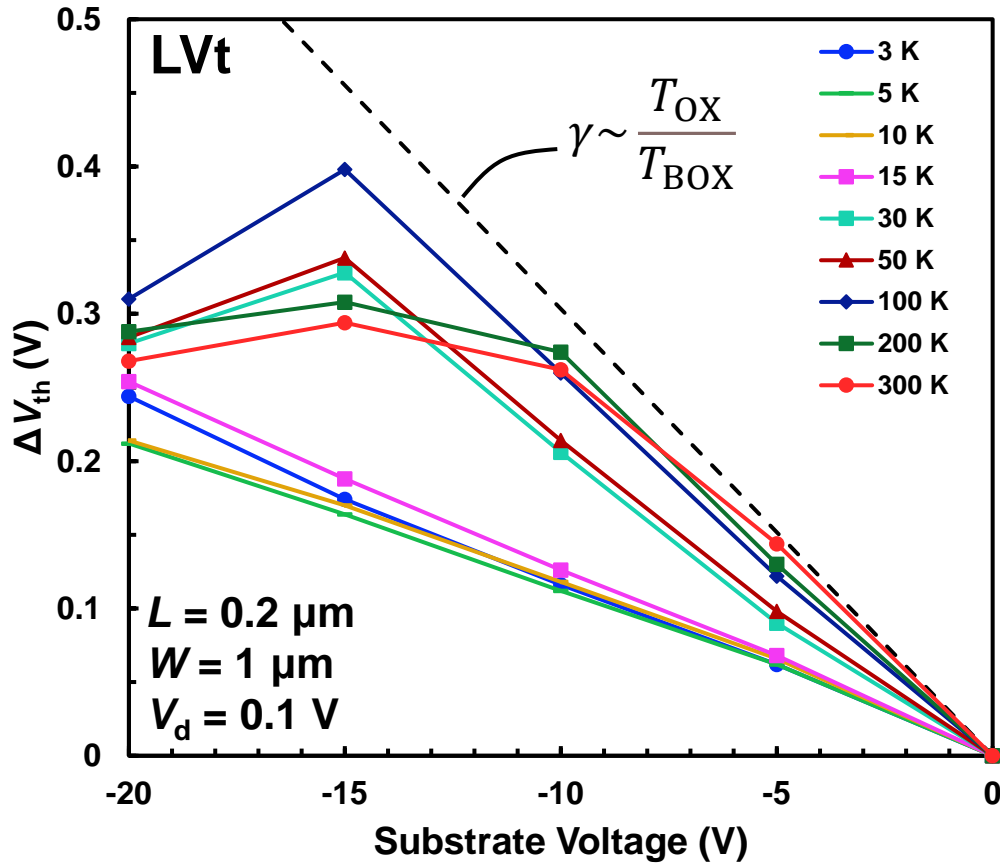
# 負の基板バイアス依存性



300 Kでは最初に大きく特性動き、 $V_{sub} = -10 \text{ V}$ で飽和  
 3 Kはほぼ一定間隔で特性シフト

しきい値シフト量は温度が下がると (15 K以下で) ほぼ一定に

# チャンネル不純物濃度依存性



チャンネル不純物濃度 : LVt > ULVt

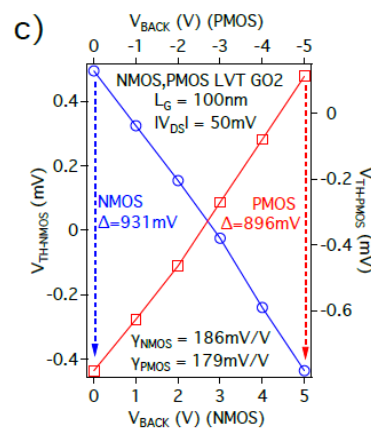
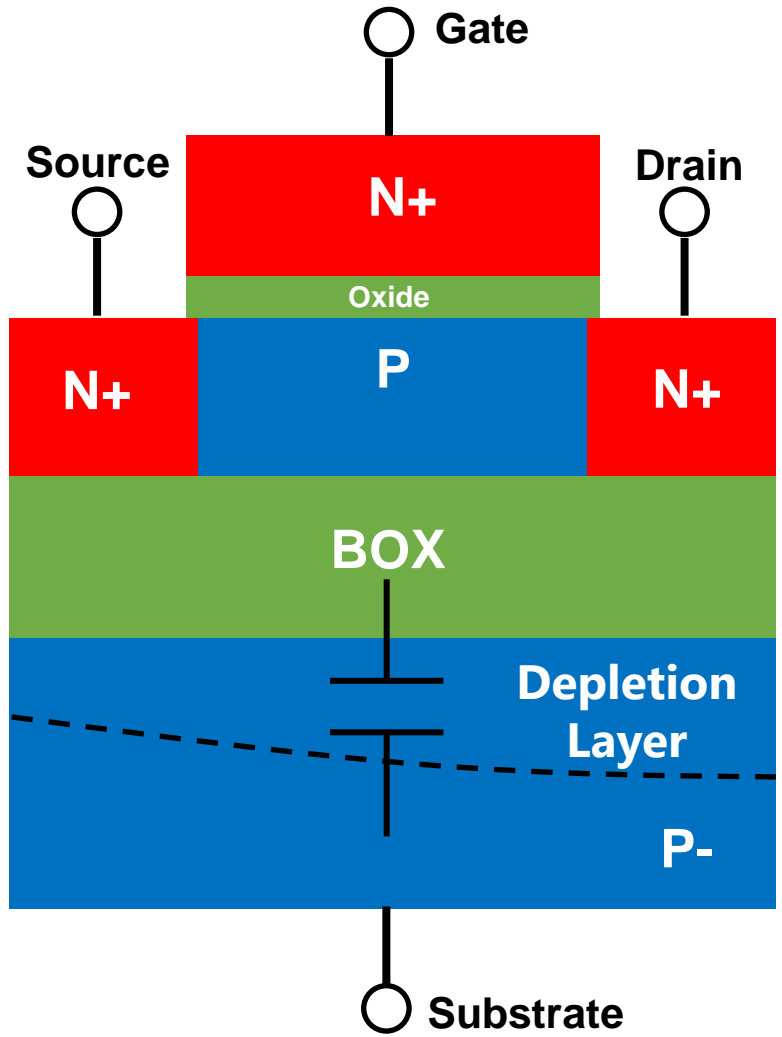
FD-SOIの理想的なボディ効果係数 $\gamma$ と比較すると半分程度の傾き（シフト量）になっている  
 ULVt（LVtより完全空乏化しやすいはず）でも低温になると傾き悪くなりほぼ一定に

# ボディ効果係数変動の想定原因

## <想定要因>

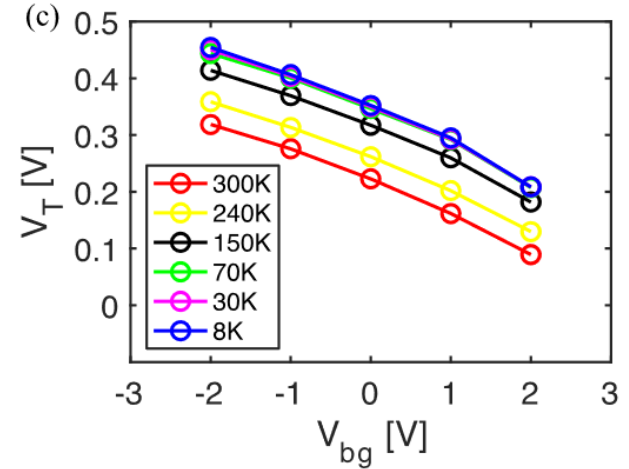
フリーズアウト? によって  
**Box下の空乏層容量が変動** → **ボディ効果係数 $\gamma$ が変動?**

先行研究では温度による $\gamma$ への影響はほとんど無い  
 → プロセス依存?



“The measured GO2 body-factors at 4.3 K are close to the room temperature values: 183 and 178 mV/V for NMOS and PMOS, respectively.”

H. Bohuslavskyi, Doctoral thesis, p. 77, Université Grenoble Alpes, 2019.



F. A. Mamun, et al., IEEE T-ED, vol. 69, no. 10, pp. 5417-5423, Oct. 2022.

## <先行研究との違い>

- Si膜厚、Box膜厚 (先行研究はより薄い)
- 裏面不純物ドーブ (しきい値制御用のドーブ有?)

# まとめ

## PN-Body Tied SOI-FETとCryo-CMOSの研究進捗について紹介

### <PNBT SOI-FET>

- Arイオン注入によるヒステリシス制御
  - **DG PNBT SOI-FETにおいて、ヒステリシスを抑えつつsteep SSを実現**
- PNBT Diodeの整流特性
  - **逆方向バイアス時にも過渡的に電流が流れてしまう現象について解析**

### <Cryo-CMOS>

- 極低温下における基板バイアス時の挙動
  - **正バイアス時は履歴効果、負バイアス時は基板バイアス効果係数の変動が発生**